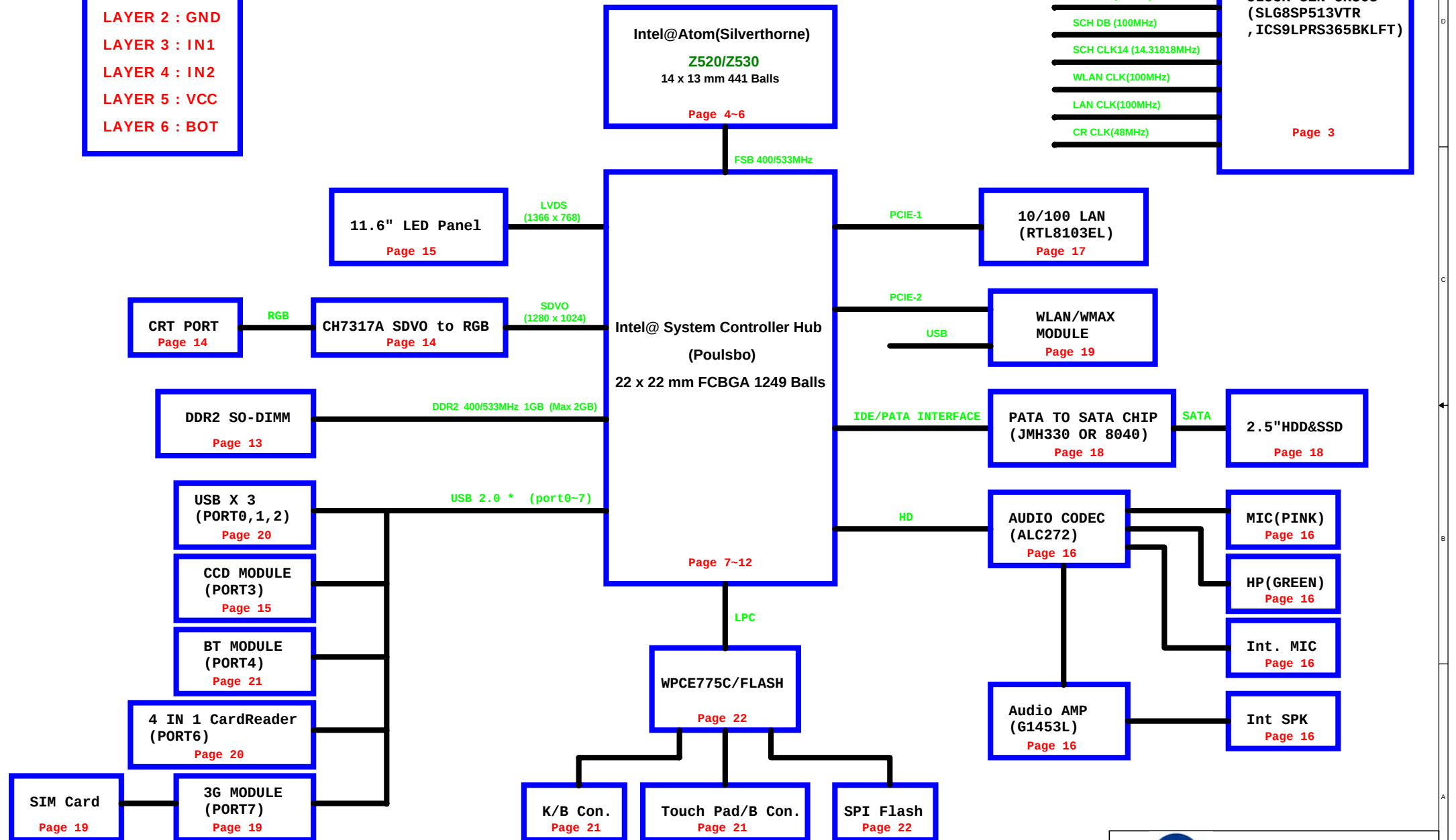


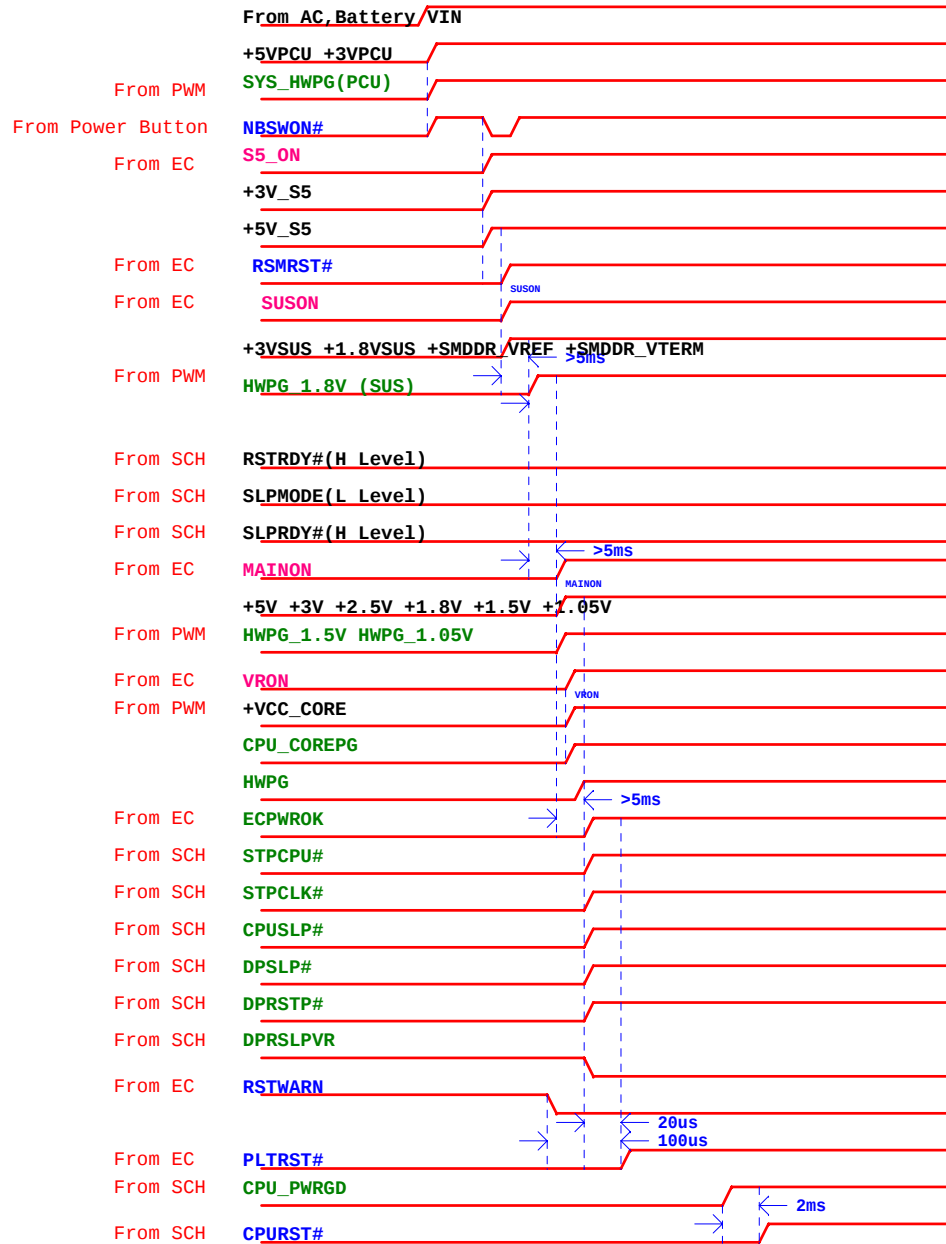
ZA3 PCB STACK UP

LAYER 1 : TOP
LAYER 2 : GND
LAYER 3 : IN1
LAYER 4 : IN2
LAYER 5 : VCC
LAYER 6 : BOT

ZA3(11.6") Block Diagram



ZA3 Power On Sequence



BOM naming rule

Items	Function	Name	Description
1	PATA TO SATA BRIDGE	8040@	Marvell 88SE8040
2	PATA TO SATA BRIDGE	330@	Jmicron JMH330
3	3G Module	3G@	
4	FAN Module	FAN_PWM@	PWM FAN
5			
6			

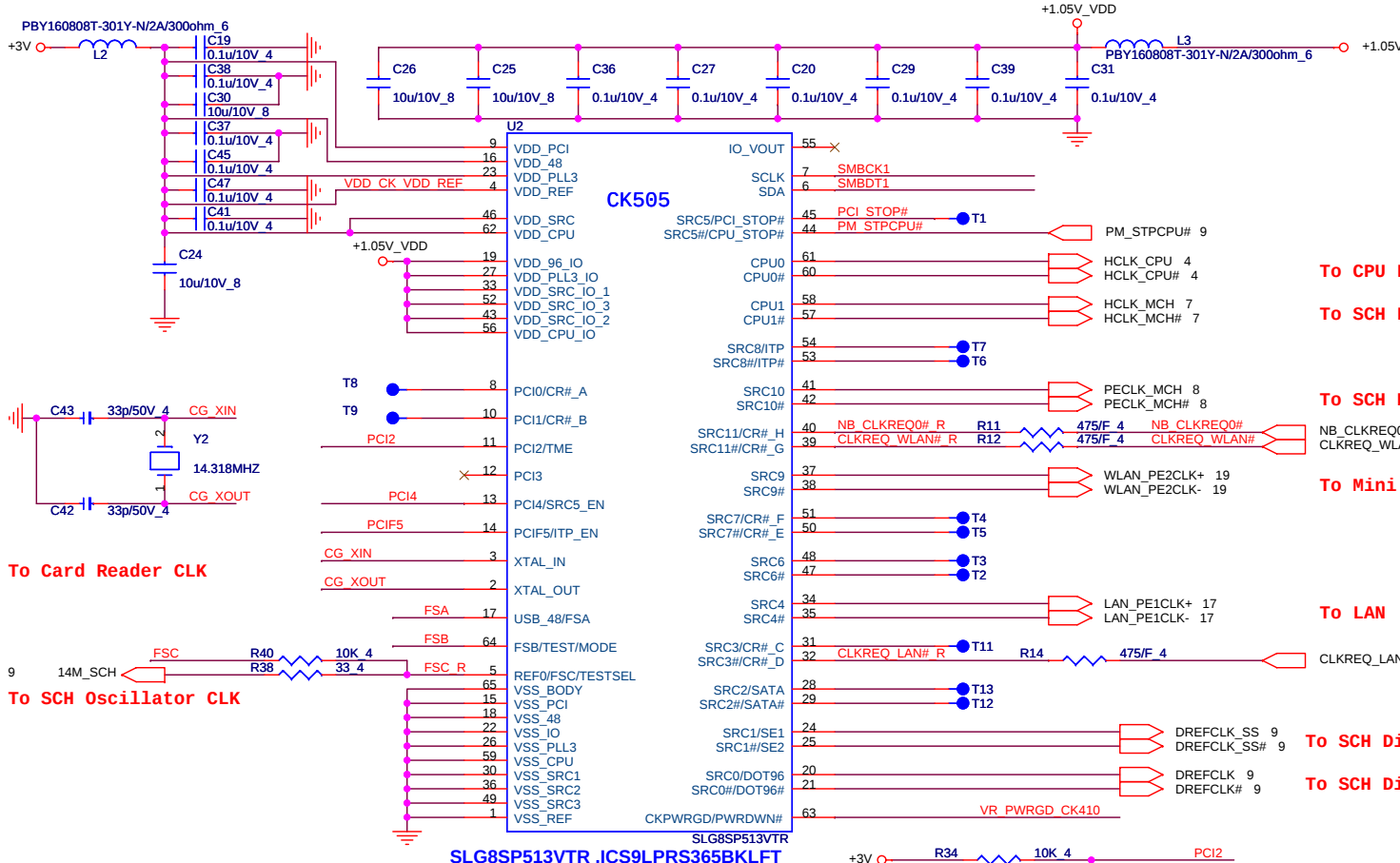
Poulsbo SCH SMBUS Table

	CLK GEN	RAM	Mini Card (WLAN/WMAX)	Mini Card (3G)
(SMB_DATA) / (SMB_CLK) (+3V)	V	V	V	V
Power Plane	+3V	+3V	+3V	+3VSUS
MOS CKT	Reserve	Reserve	Reserve	Reserve

EC SMBUS Table

	Battery	CPU thermal Sensor	EC EEPROM
EC775 SDA1 / SCL1 (+3VPCU)	V		
EC775 SDA2 / SCL2 (+3VPCU)		V	V
Power Plane	+3VPCU	+3V	+3VPCU
MOS CKT	X	Stuff	X

Clock Generator(CLK)



To Card Reader CLK

To SCH Oscillator CLK

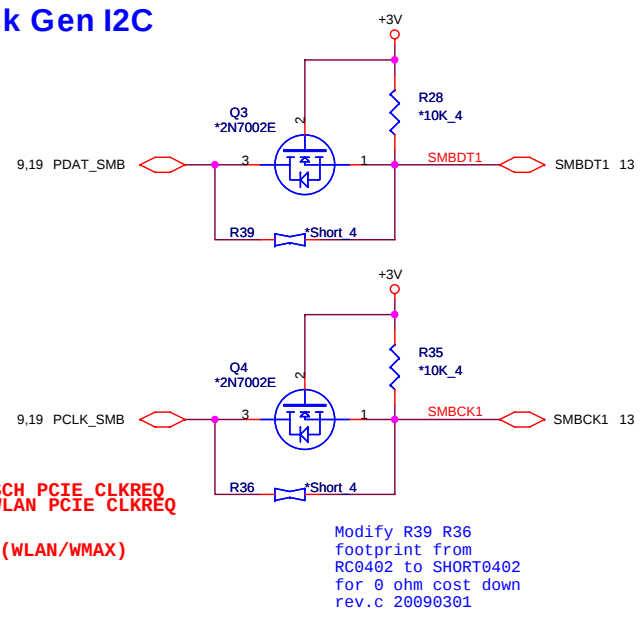
	SLG8SP513VTR (AL8SP513000)	ICS9LPRS365 (ALPRS365000)	PULL HIGH	PULL DOWN
Pin 11	PCI2/TME	PCI2/TME	NO OVERCLOCKING (default)	NORMAL RUN
Pin 13	PCI4/ 27_Select	PCI_4/ SEL_LCDCLK#	PIN 24/25 IS 27MHz	PIN 24/25 IS SRC/DOT (default)
Pin 14	PCIF-5/ITP_EN	PCIF-5/ITP_EN	PIN 53/54 IS CPUITP	PIN 53/54 IS SRC8 (default)

<MAIN> : SLG8SP513VTR(AL8SP513000)
<SECOND> : ICS9LPRS365BKLFT(ALPRS365000)

SEL2 SEL1 SEL0 Frequence select

FSC	FSB	FSA	CPU	SRC	PCI	States
1	0	1	100	100	33	
0	0	1	133	100	33	Default

Clock Gen I2C



To CPU FSB CLK

To SCH FSB CLK

To SCH PCIE CLK

SCH PCIE CLKREQ
WLAN PCIE CLKREQ

To Mini Card 1 (WLAN/WMAX)

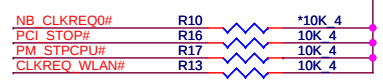
To LAN

LAN CLKREQ

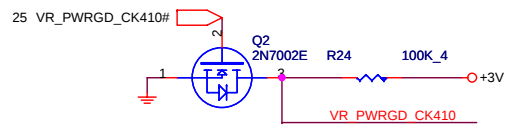
To SCH Display PLLB CLK

To SCH Display PLLA CLK

EMI



CLK GEN & PWR

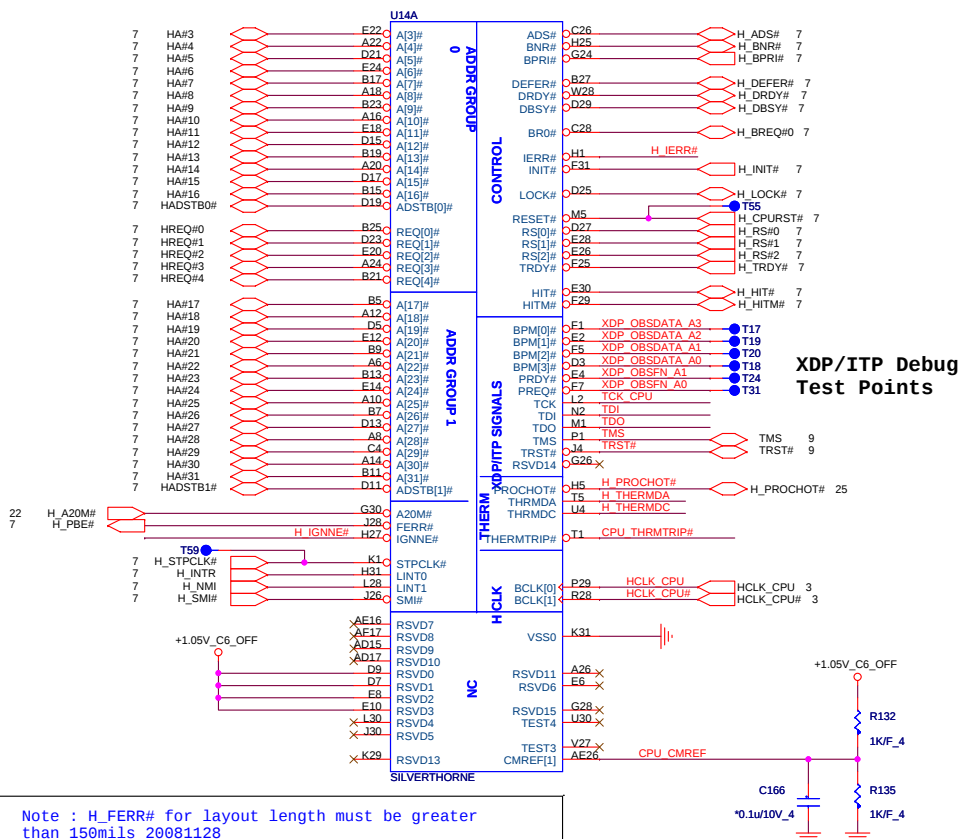


Change R43 P/N
from
CS00002JB38 to
CS31002JB28
rev.c 20090301

Quanta Computer Inc.
PROJECT : ZA3

Size	Document Number	Rev
	CLOCK GEN(CK505)	1A
Date:	Sunday, March 08, 2009	Sheet 3 of 34

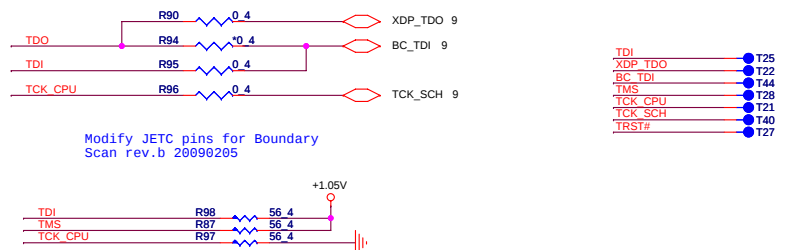
Silverthorne(CPU)



Note : H_FERR# for layout length must be greater than 150mils 20081128

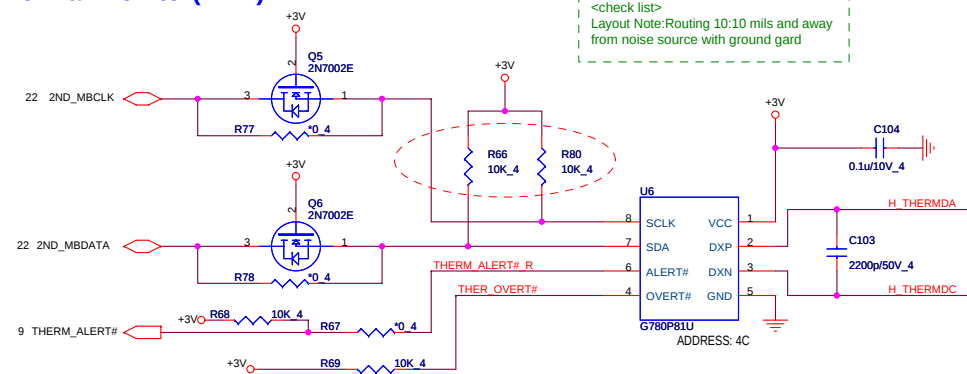


For intel suggest R115 connect to +1.05V_C6_OFF 20081218



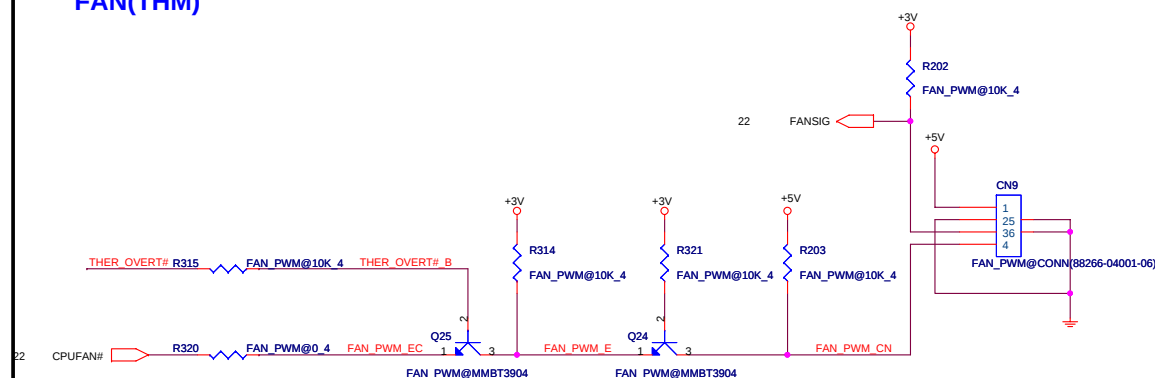
Modify JETC pins for Boundary
Scan rev.b 20090205

CPU Thermal monitor(THM)

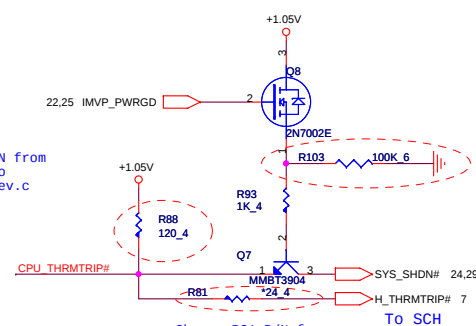


<check list>
Layout Note: Routing 10:10 miles and away
from noise source with ground gard

FAN(THM)



Thermal Trip(CPU)



Change R88 P/N from
CS05602JB17 to
CS11202JB21 rev.c
20090301

Change R81 P/N from
CS00002JB38 to
CS02402JB11 rev.c
20090301

To SCH

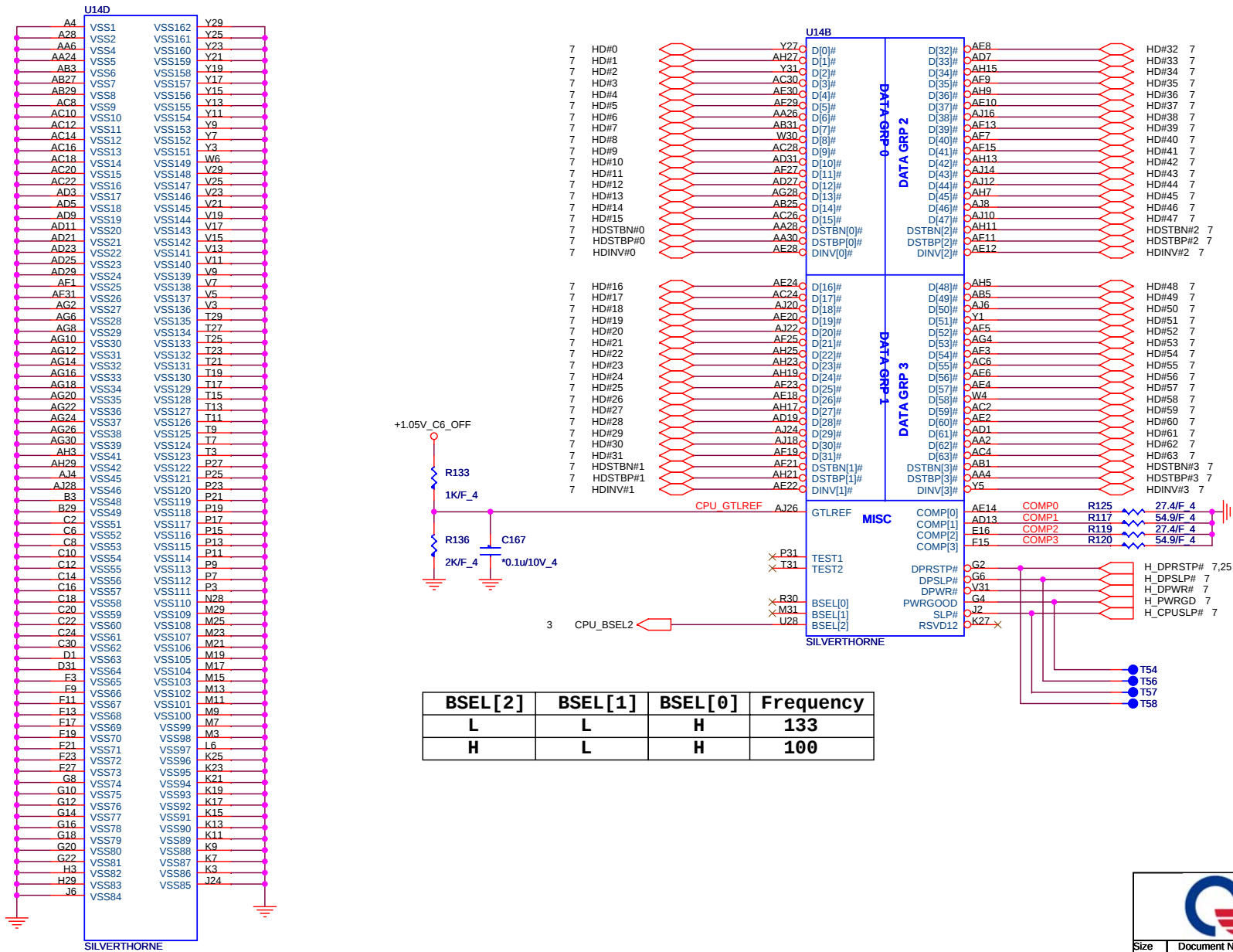
To SCH



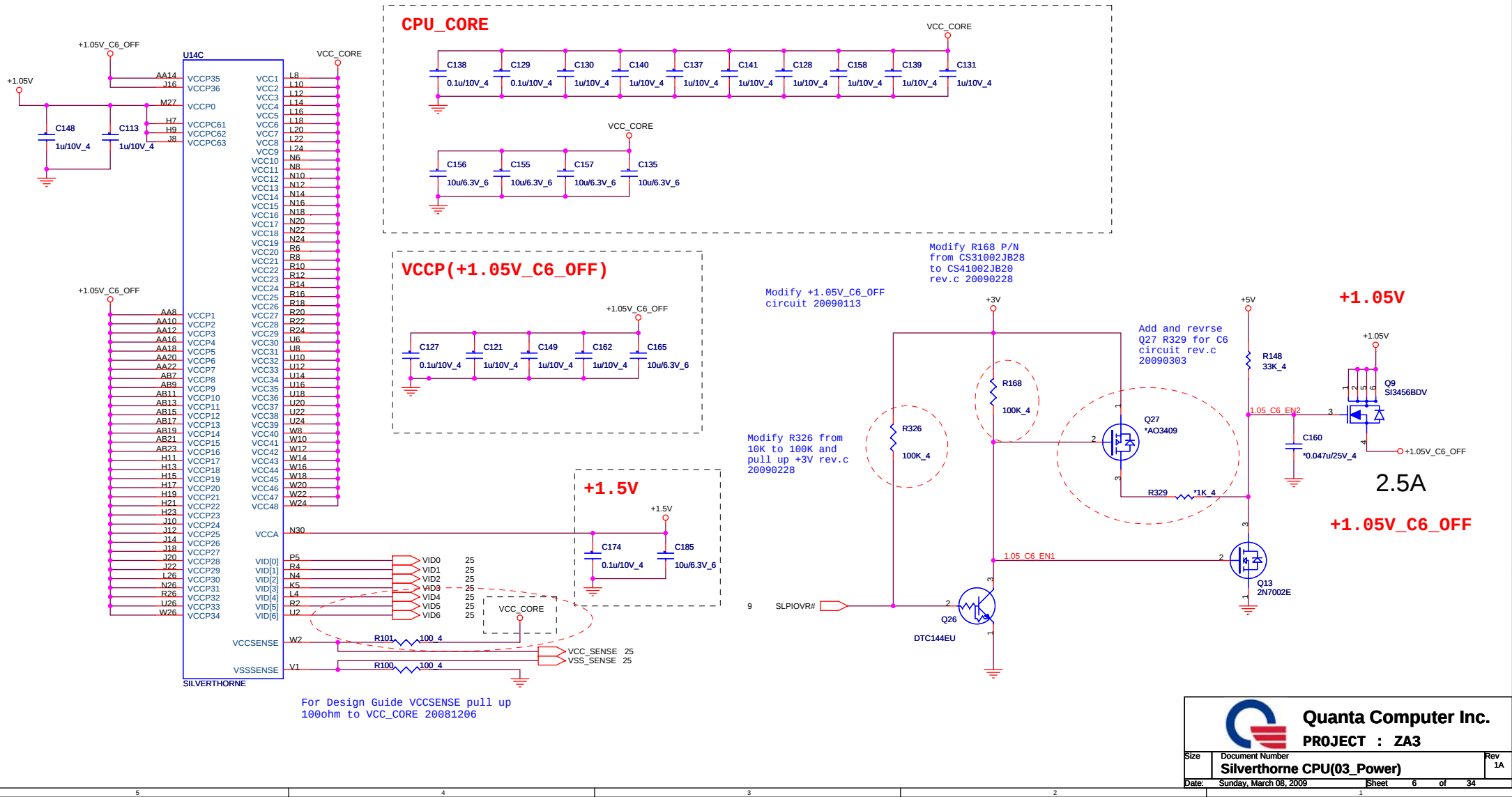
Quanta Computer Inc.
PROJECT : ZA3

Size	Document Number	Rev
	Silverthorne CPU(01_HOST)	1A
Date:	Sunday, March 08, 2009	Sheet 4 of 34

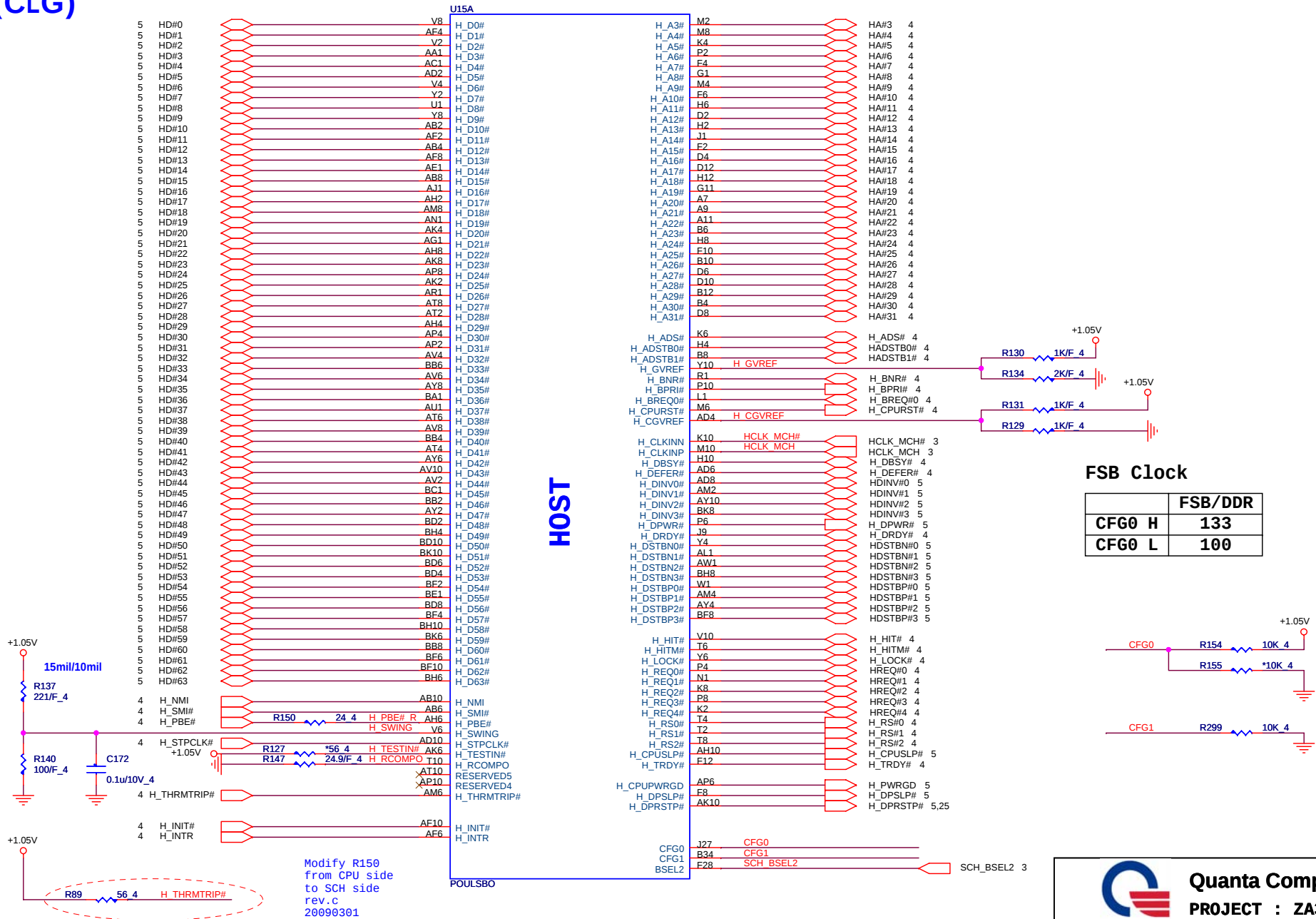
Silverthorne(CPU)



Silverthorne(CPU)



Poulsbo(CLG)

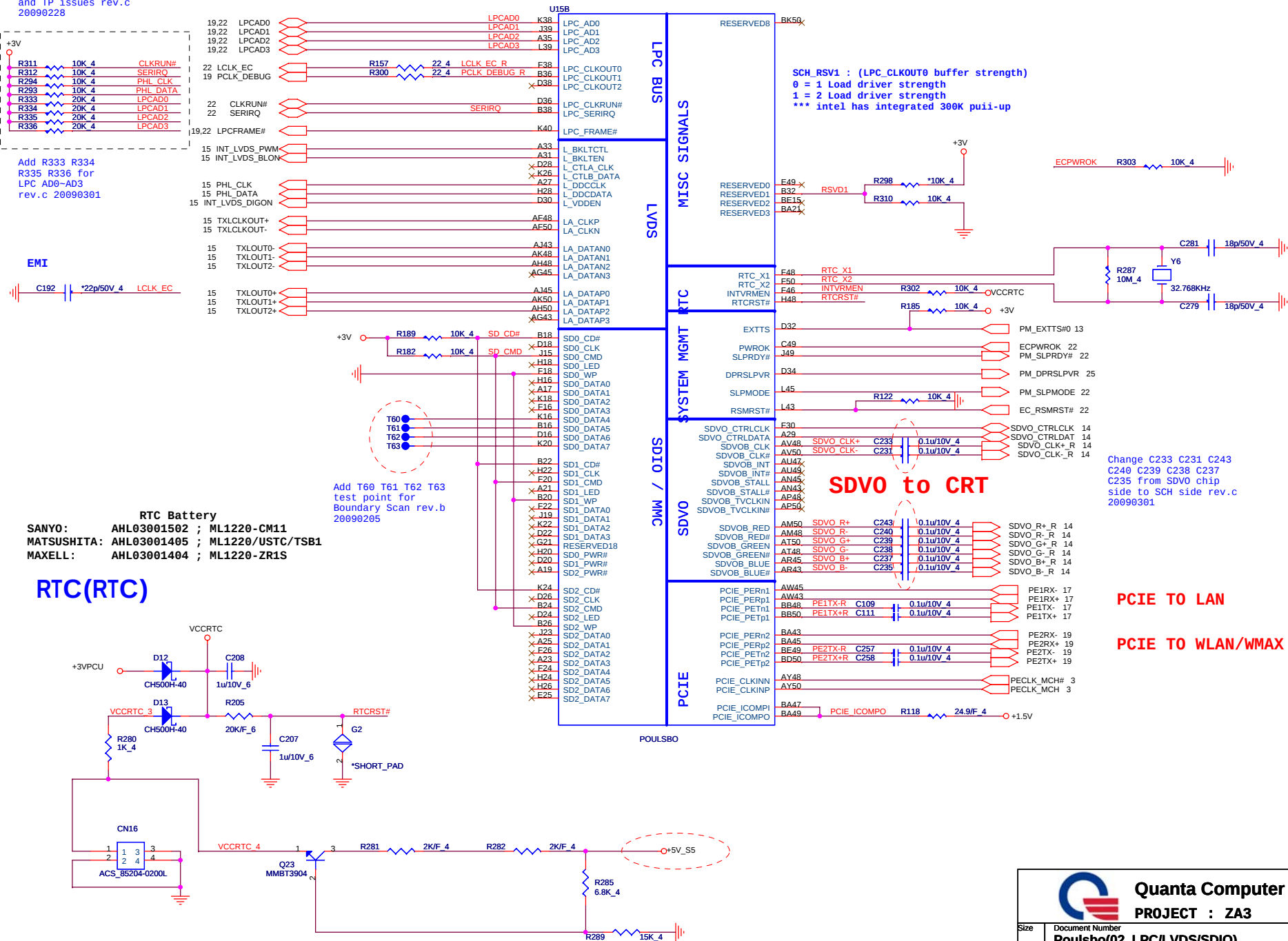


	FSB/DDR
CFG0 H	133
CFG0 L	100

	Quanta Computer Inc. PROJECT : ZA3
Document Number Poulsbo(01_HOST)	Rev 1A

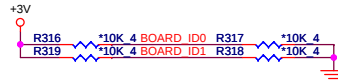
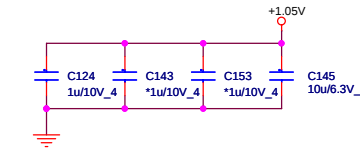
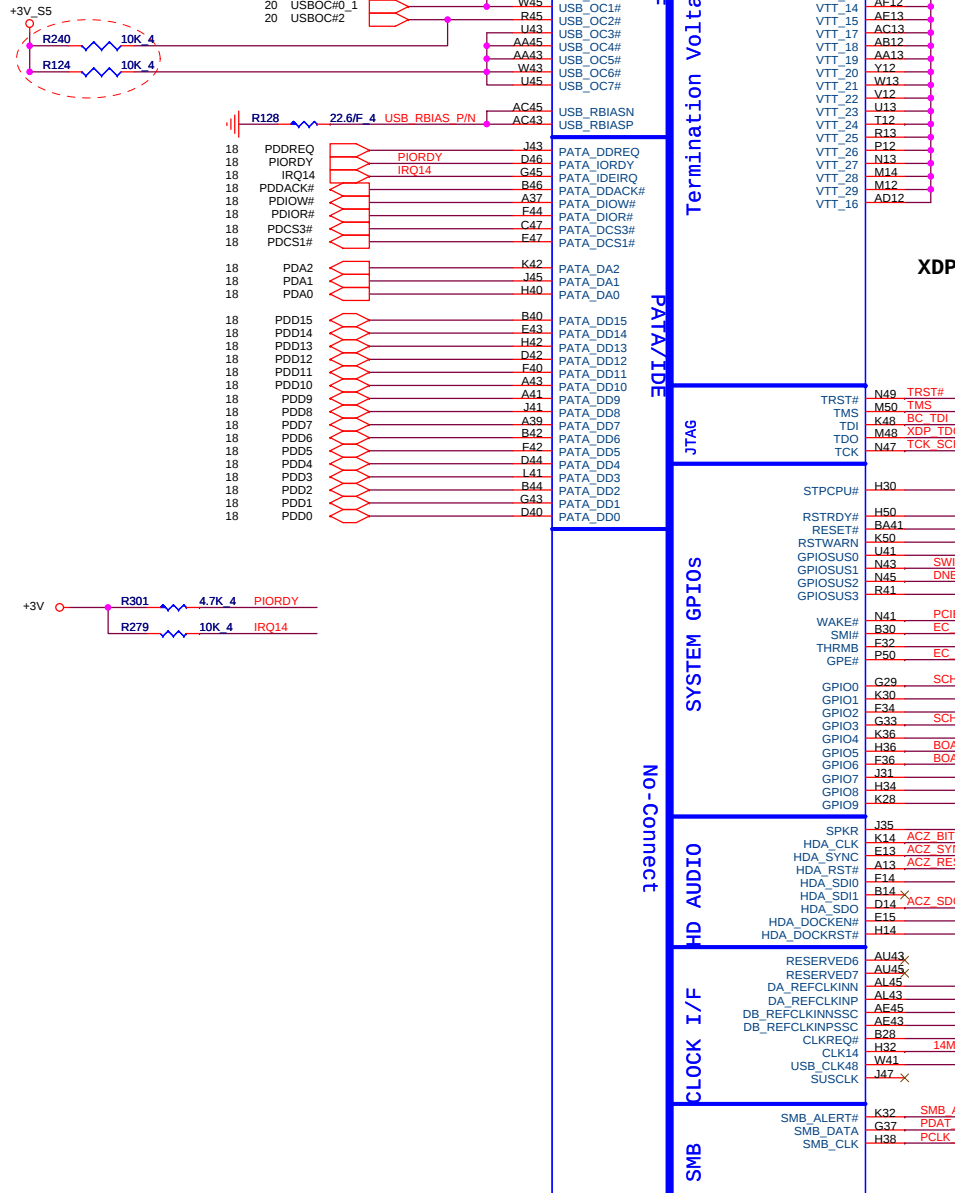
Poulsbo(CLG)

Stuff R312 for Keyboard
and TP issues rev.c
20090228



Poulsbo(CLG)

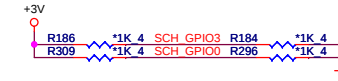
- 0--MB USB PORT1
- 1--MB USB PORT2
- 2--DB USB PORT3
- 3--CCD Module
- 4--BT Module
- 5--MINI WLAN/WMAX
- 6--CARD READER
- 7--MINI 3G Module



ID1	ID0	Functions
0	0	
0	1	
1	0	
1	1	

: Default

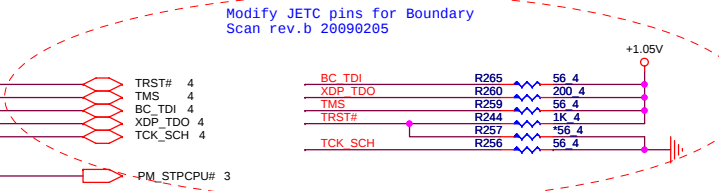
Change R186 R184 R309 R296
P/N from CS31002JB28 to
CS21002JB34 rev.c 20090301



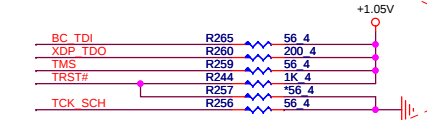
GPIO3	GPIO0	CMC Base Add.
0	0	FFFF000h
0	1	FFFC000h
1	0	FFFD000h(*)
1	1	FFFE000h

: Default

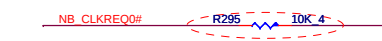
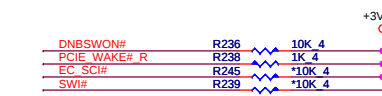
XDP/ITP Debug Test Points



Modify JETC pins for Boundary
Scan rev.b 20090205



Change R297 from
+3V_S5 to +3V
for SMI# rev.c
20090304



For intel suggest add R295 pull
down 20081218

No-Connect

CLOCK I/F

SMB

POULSBO

SCH GFX Clock
SCH GFX SS Clock

Del RN8 and Add R337 R338 to SCH
SMBUS rev.c 20090301

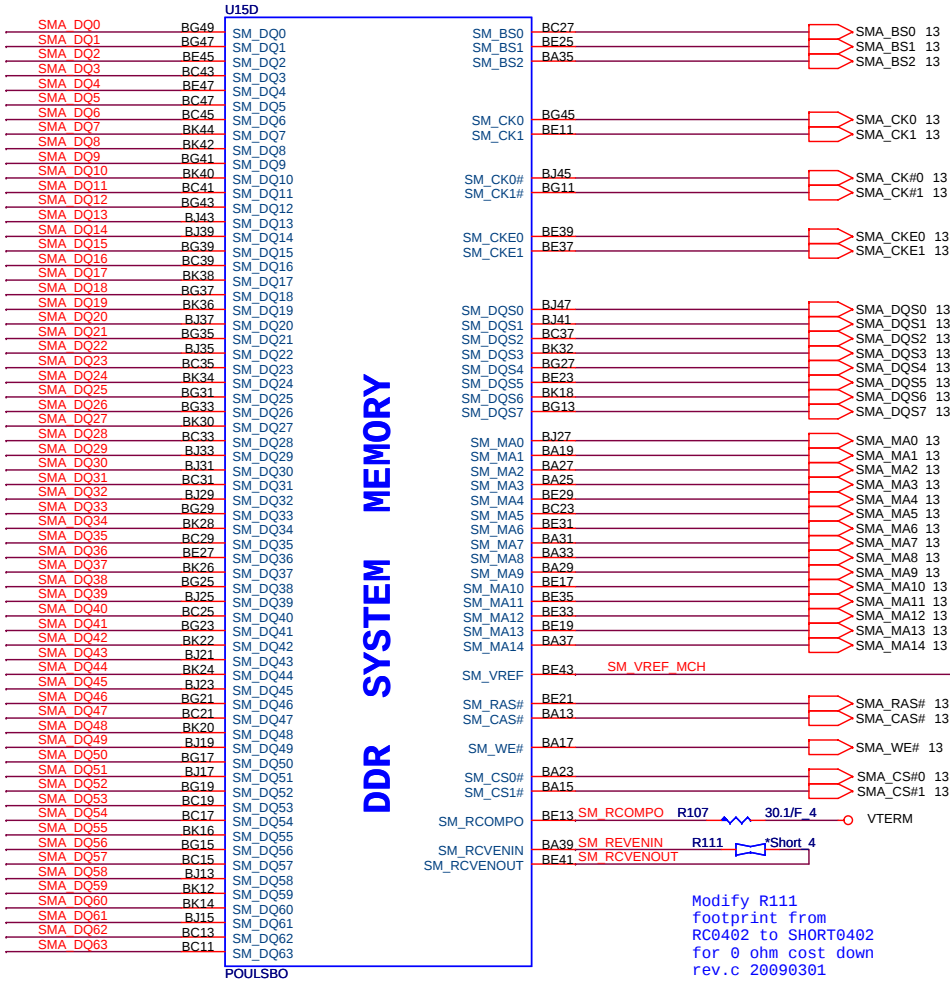


Quanta Computer Inc.
PROJECT : ZA3

Size	Document Number	Rev
	Poulsbo(03_USB/PATA/HD)	1A
Date:	Sunday, March 08, 2009	Sheet 9 of 34

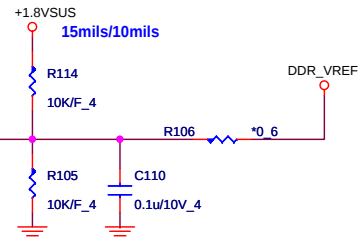
Poulsbo(CLG)

13 SMA_DQ[63..0]

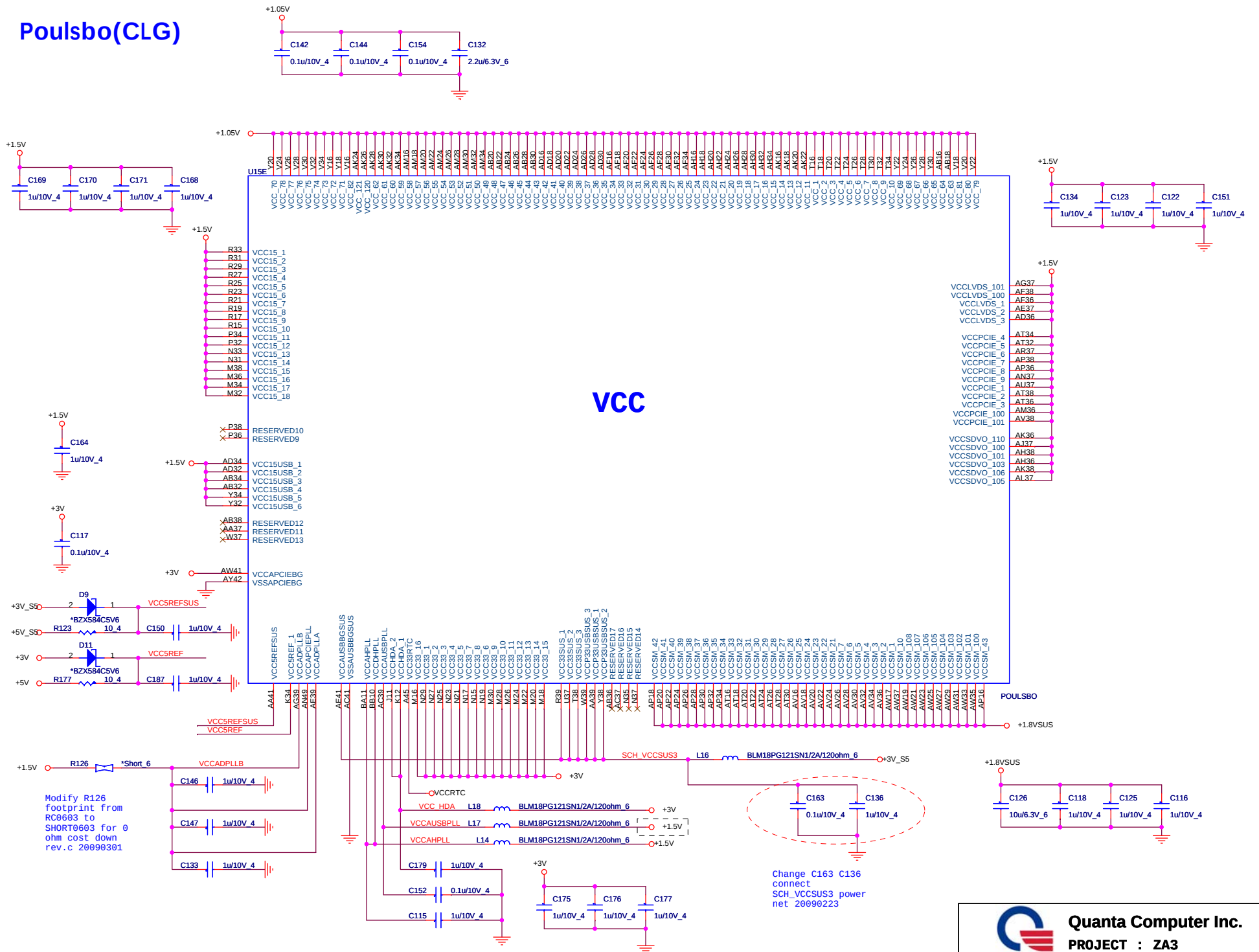


DDR SYSTEM MEMORY

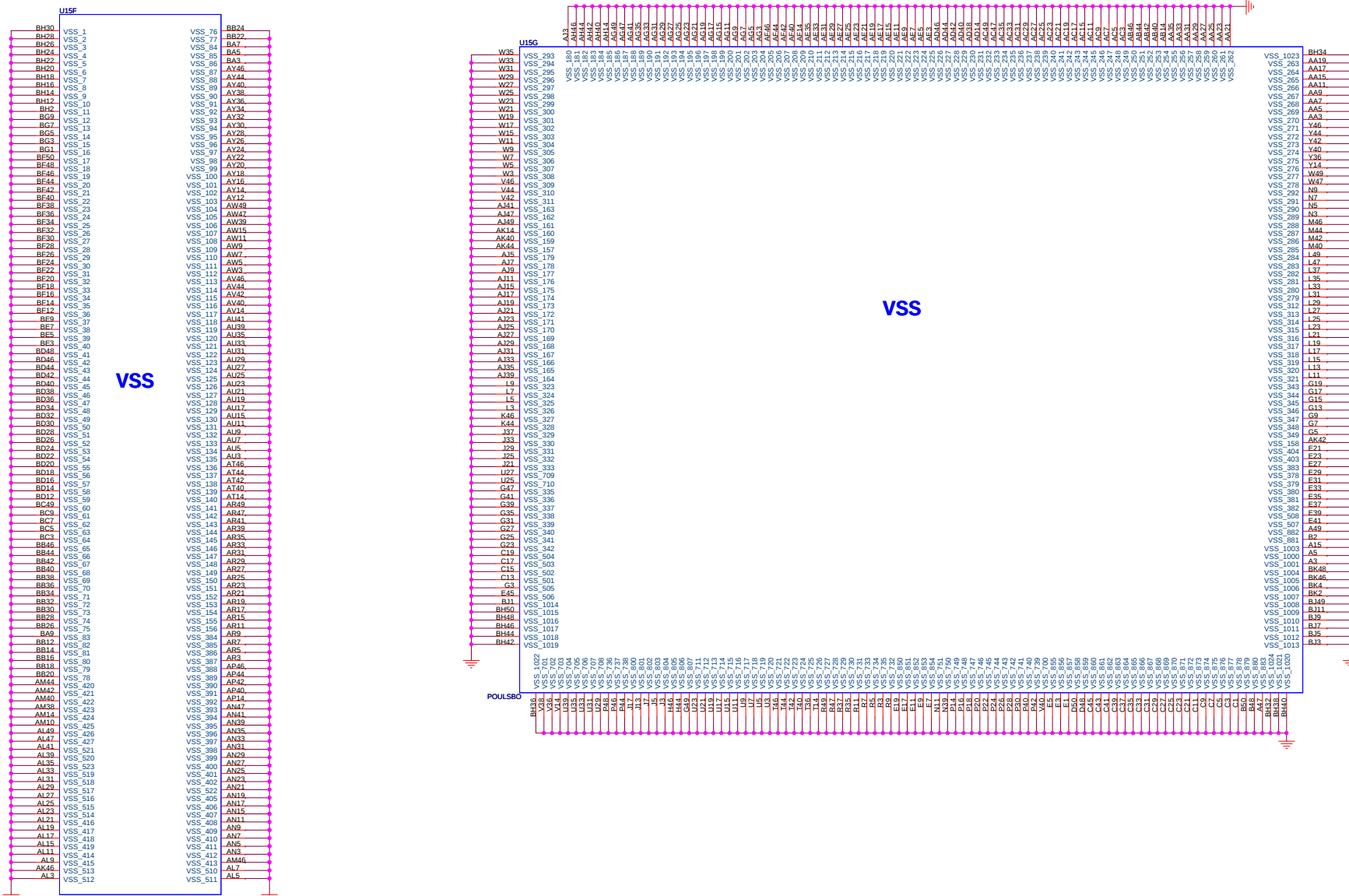
Modify R111
footprint from
RC0402 to SHORT0402
for 0 ohm cost down
rev.c 20090301



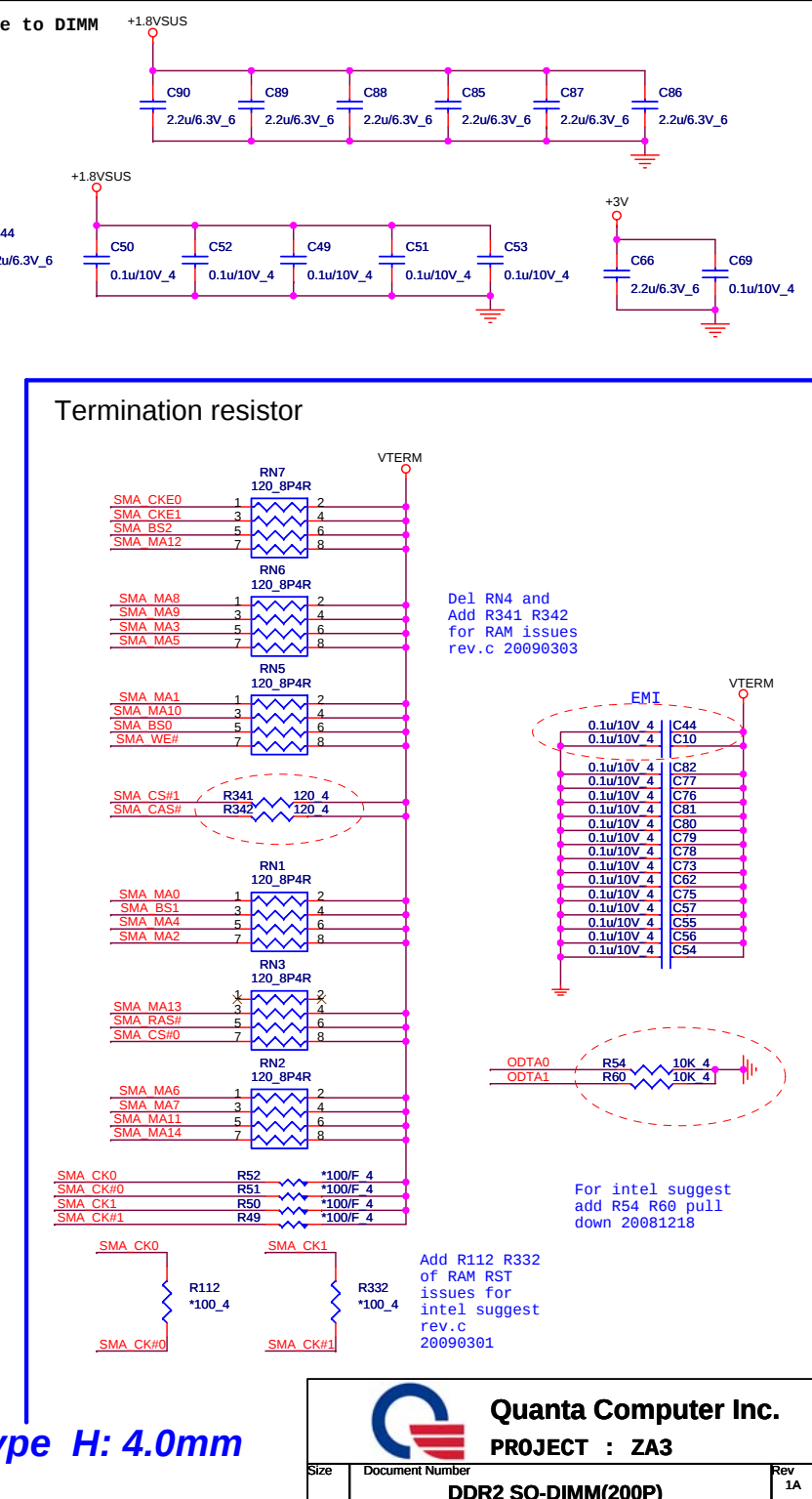
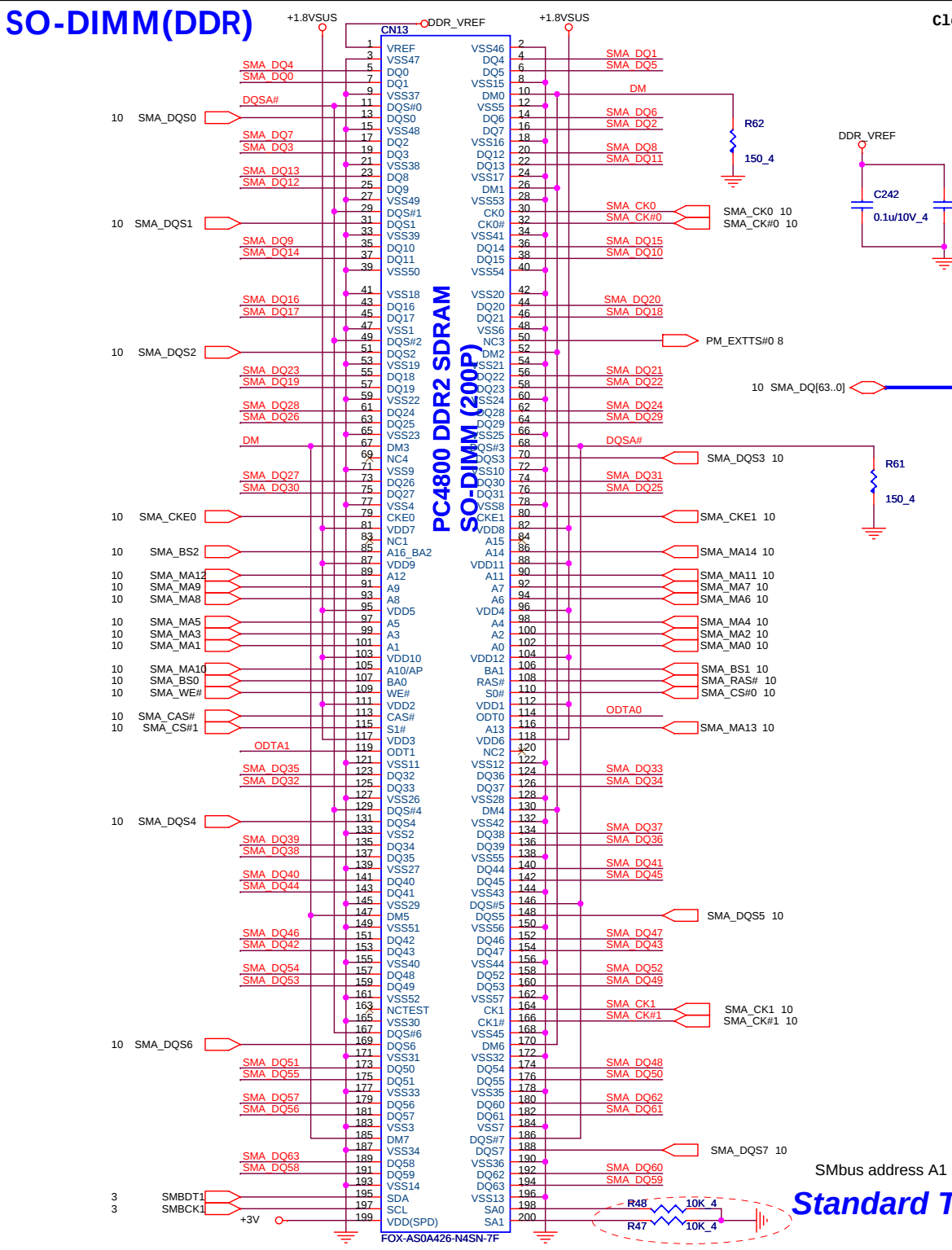
Poulsbo(CLG)



Poulsbo(CLG)



SO-DIMM(DDR)



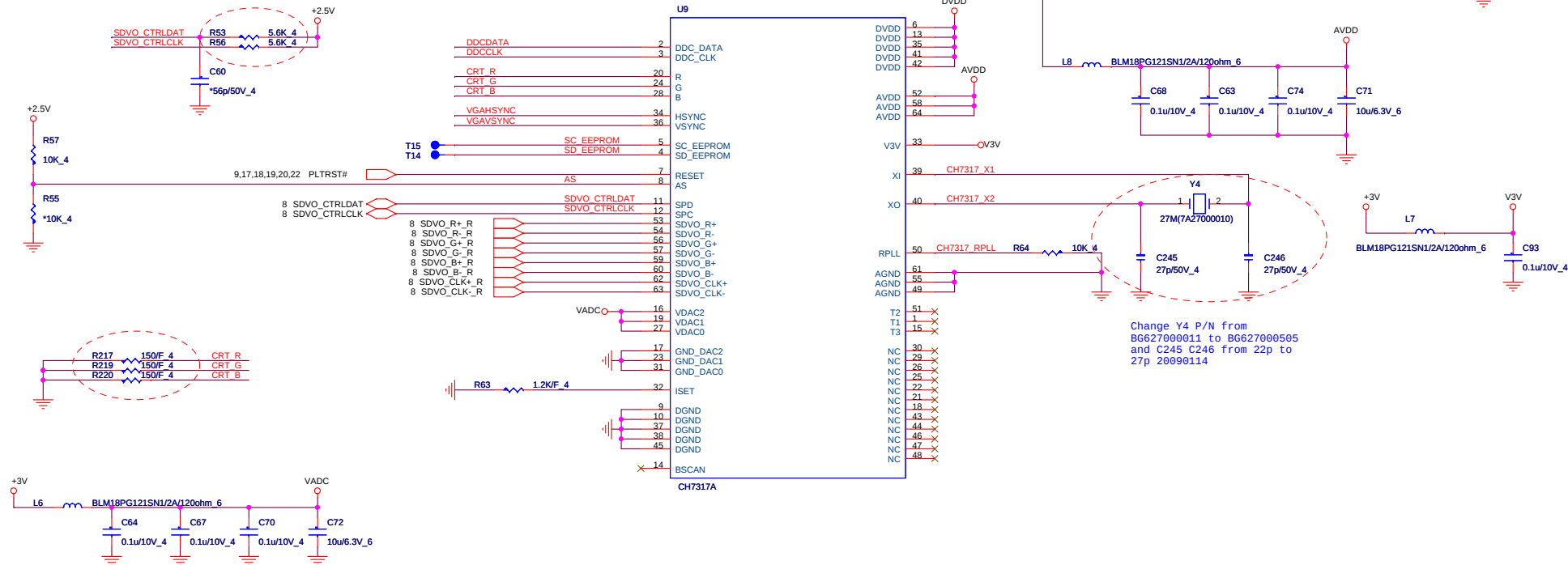


Quanta Computer Inc.
PROJECT : ZA3

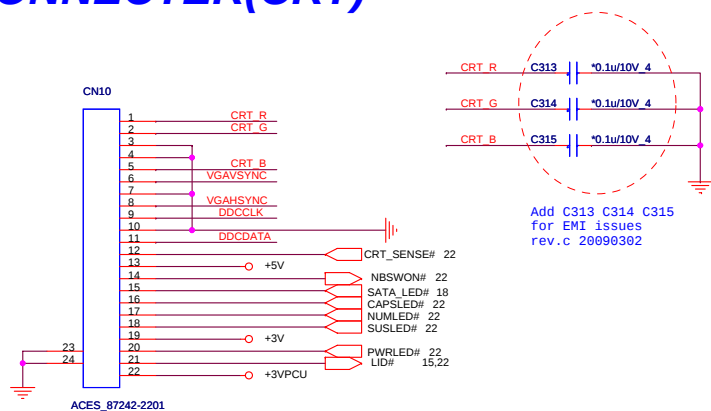
Size	Document Number	Rev
	DDR2 SO-DIMM(200P)	1A
Date:	Sunday, March 08, 2009	Sheet 13 of 34

SDVO To CRT(CRT)

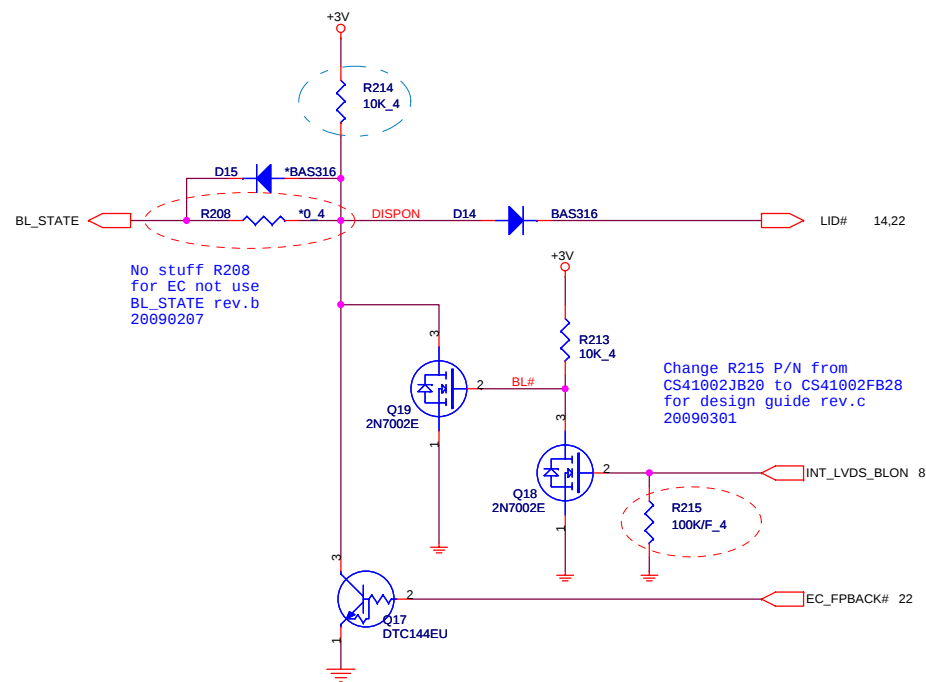
For vender FAE check, Change R53
R56 from 3.9K to 5.6K 20081205



CRT DB CONNECTER(CRT)

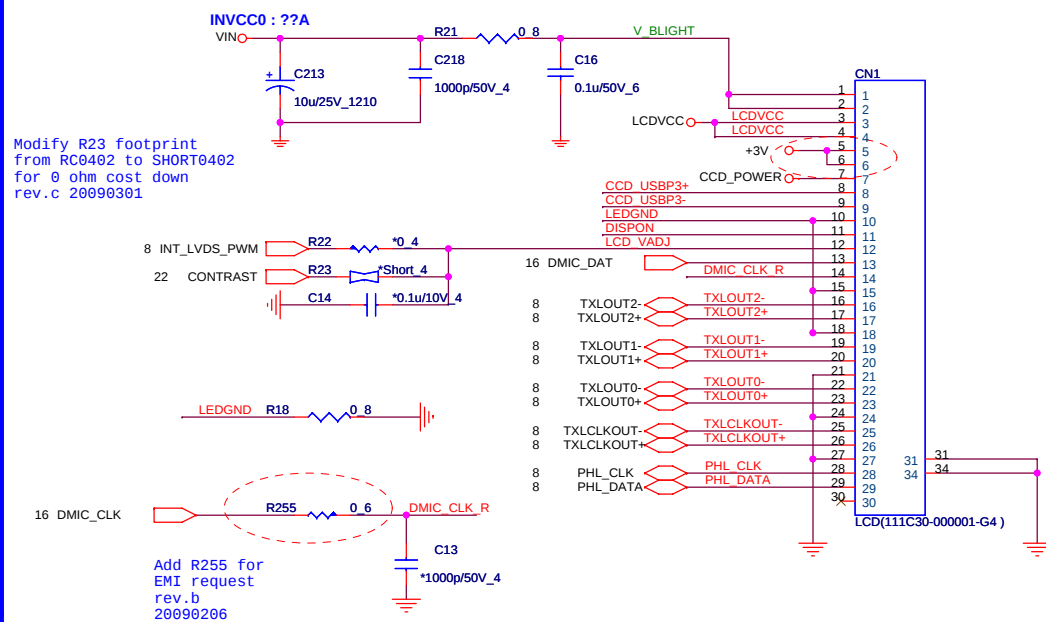


Backlight Control(LDS)

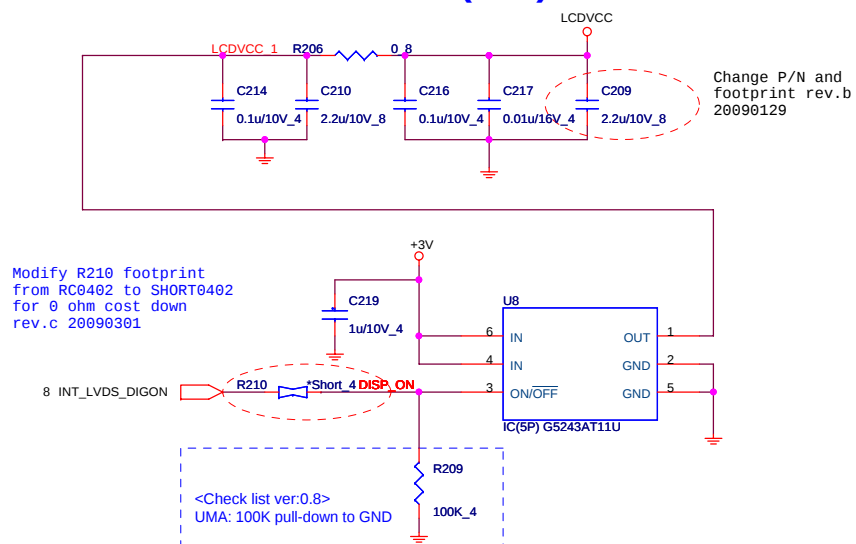


LED Panel(LDS)

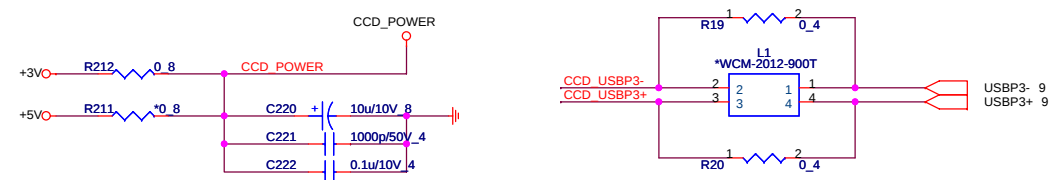
V_BLIGHT : ?V ?A



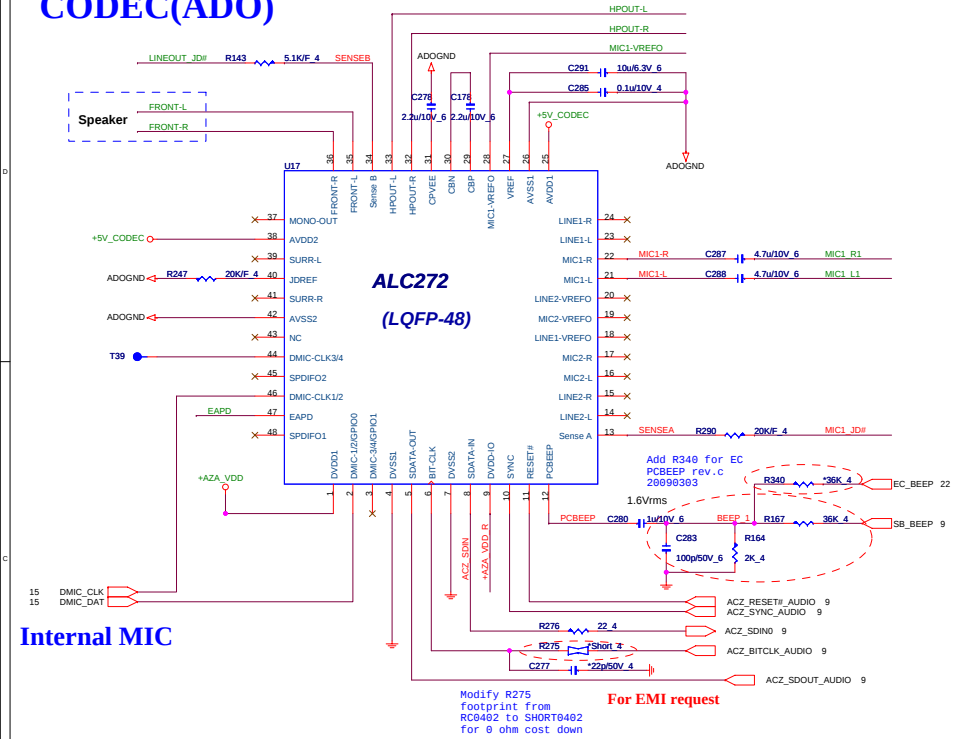
LED Panel POWER SWITCH(LDS)



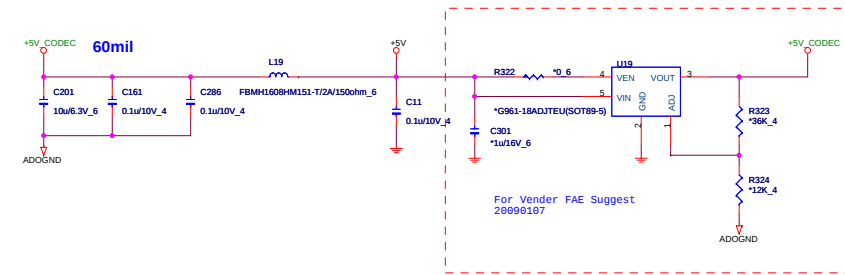
Camera(CCD)



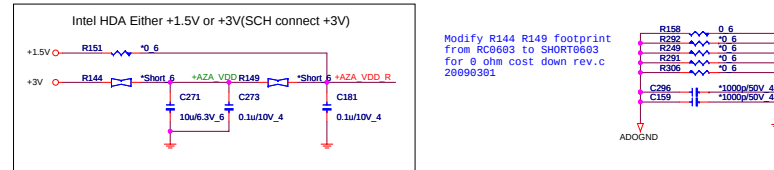
CODEC(ADO)



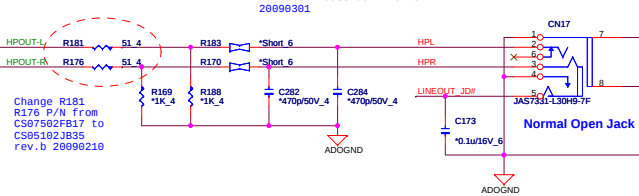
Codec Power(ADO)



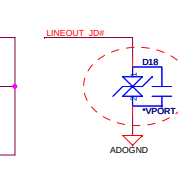
HDA Power(ADO)



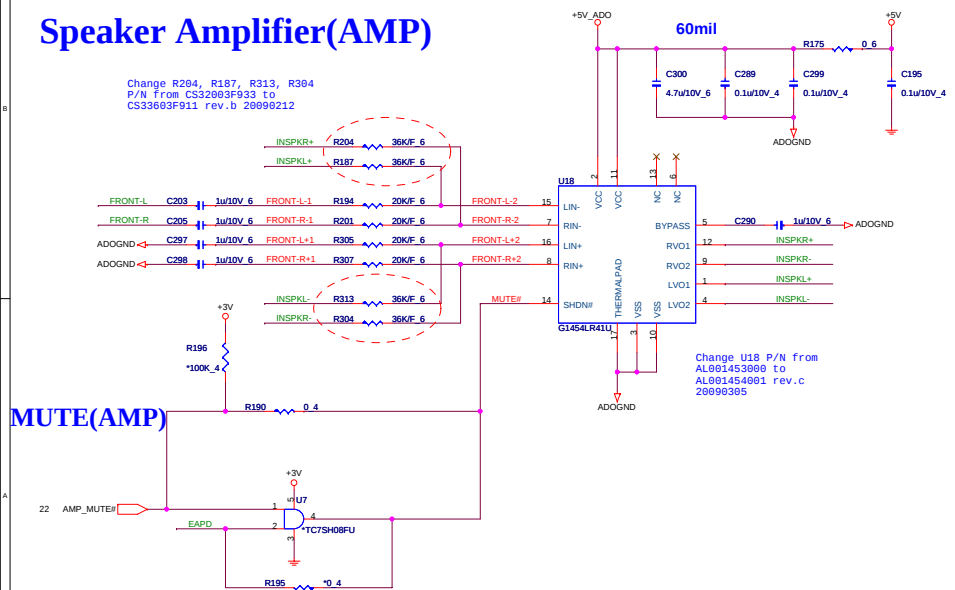
HP_Green(AMP)



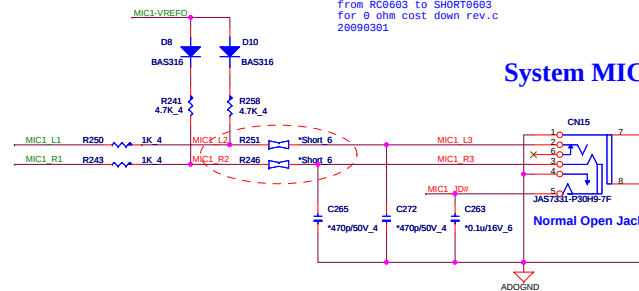
HP_Green ESD(EMC)



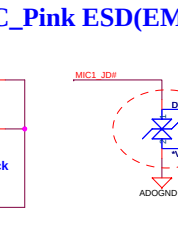
Speaker Amplifier(AMP)



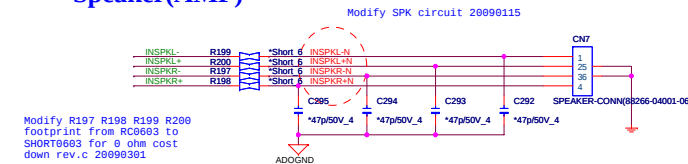
System MIC_Pink(AMP)



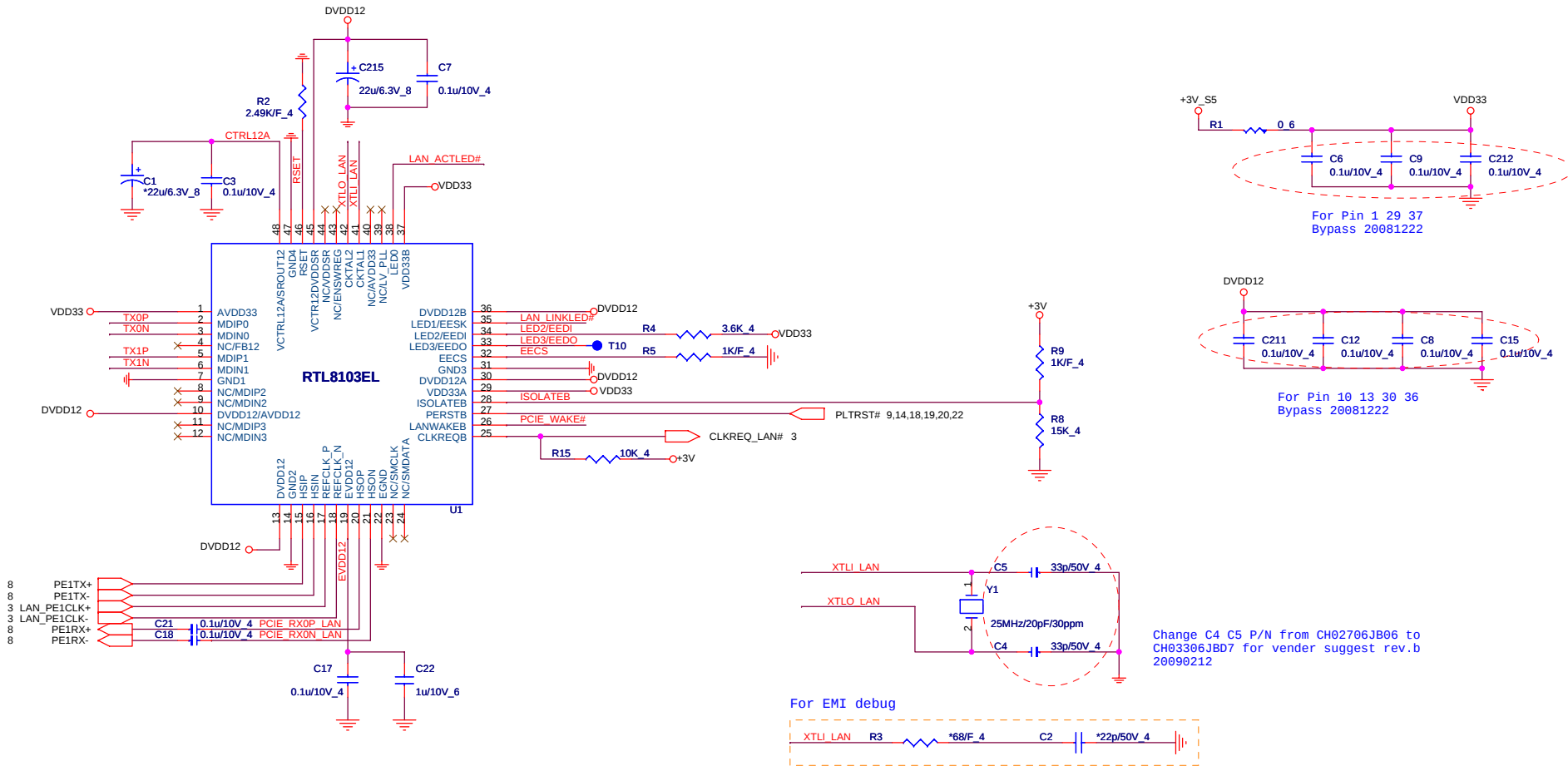
System MIC_Pink ESD(EMC)



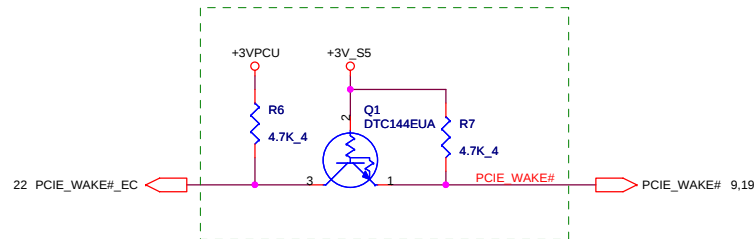
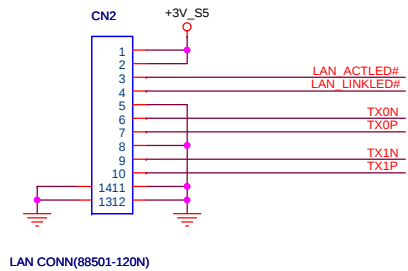
Speaker(AMP)



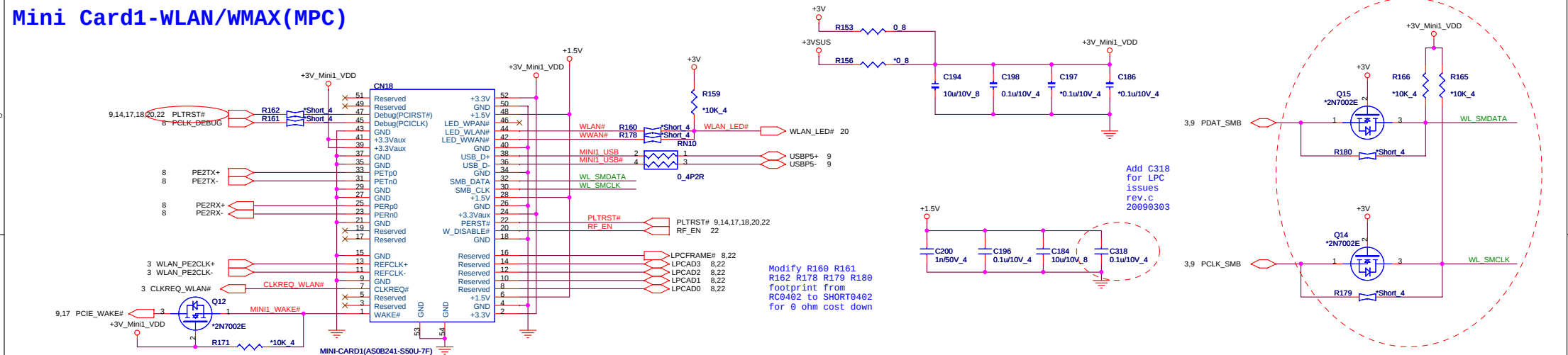
LAN RTL8103EL (LAN)



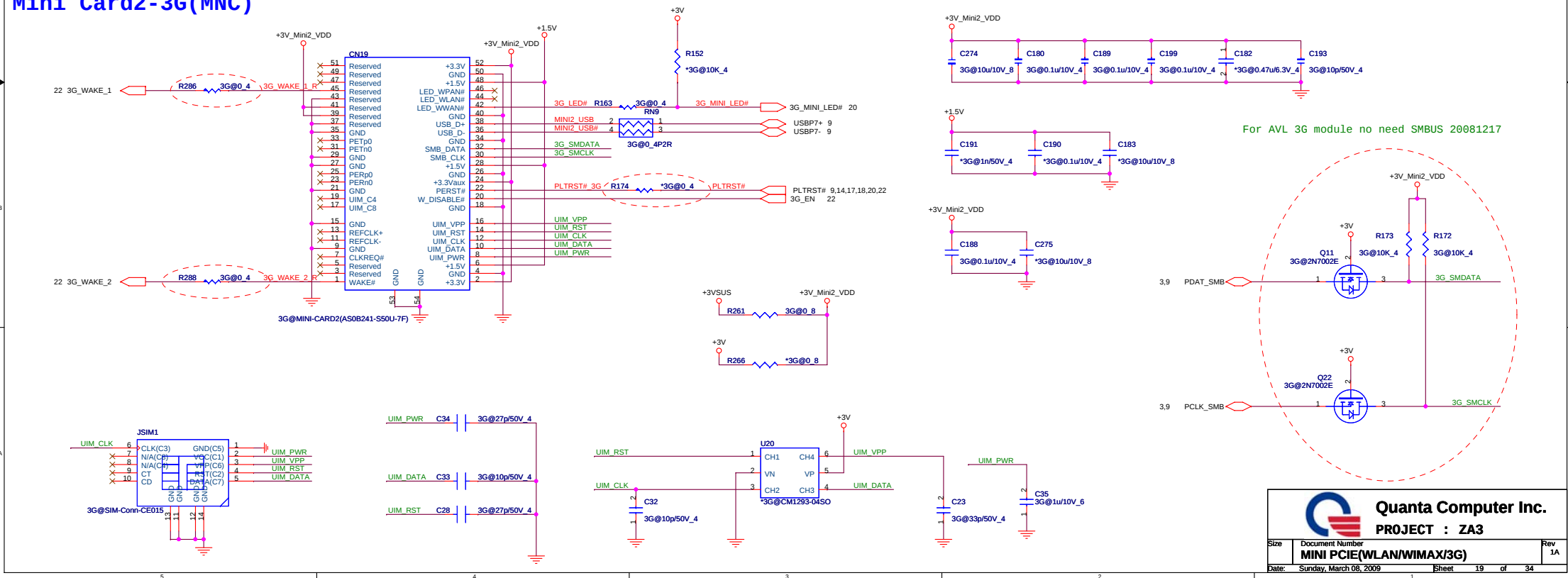
LAN D/B CONNECTER(LAN)



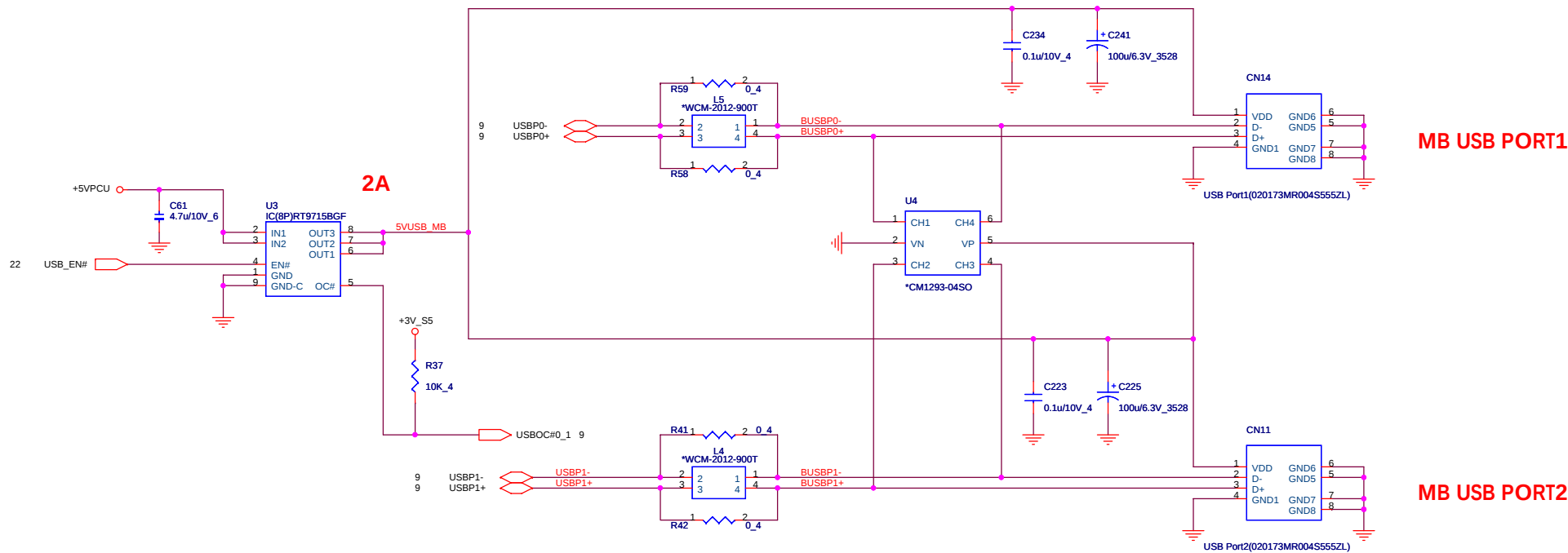
Mini Card1-WLAN/WMAX(MPC)



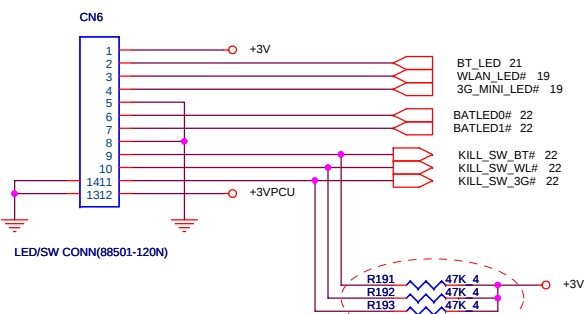
Mini Card2-3G(MNC)



MB USB PORTS(USB)

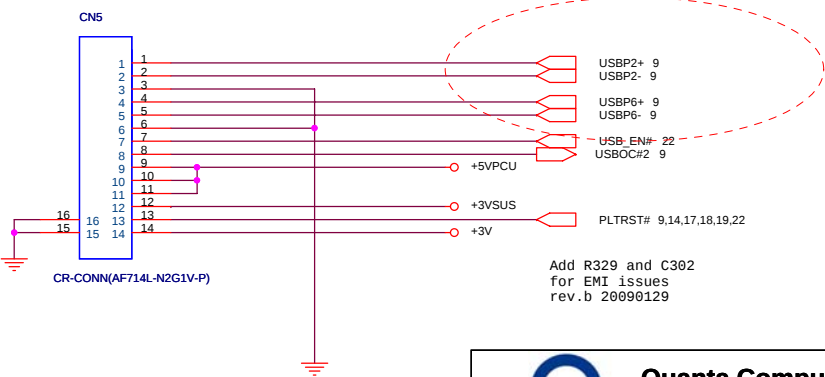


LED DB CONNECTER(UIF)



EC GPIO	Button
KILL_SW_WL#(GPIO57 PIN33)	WLAN Switch
KILL_SW_3G#(GPIO60 PIN34)	3G Switch
KILL_SW_BT#(GPIO12 PIN13)	BT Switch

Card Reader/USB DB CONNECTER(MMC)



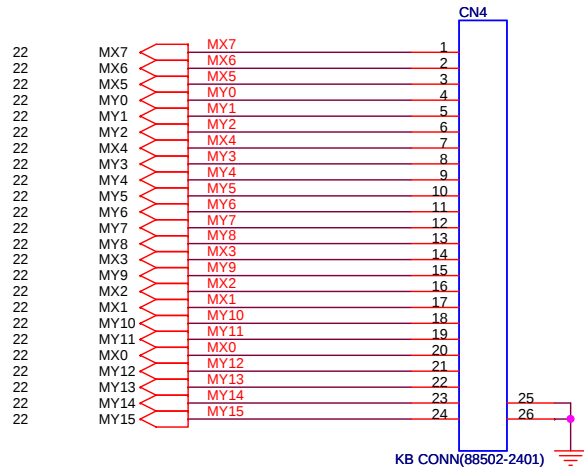
Add R329 and C302
for EMI issues
rev.b 20090129



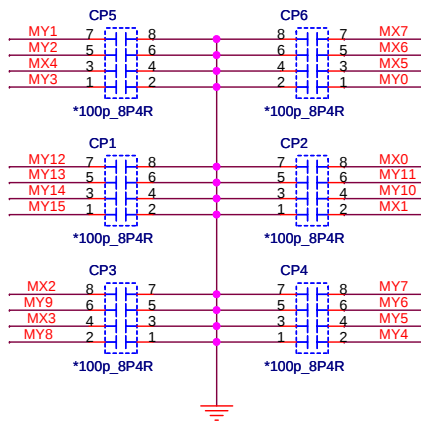
Quanta Computer Inc.
PROJECT : ZA3

Size	Document Number	Rev
	USB/SD_LED AND CR_USB DB	1A
Date:	Sunday, March 08, 2009	Sheet 20 of 34

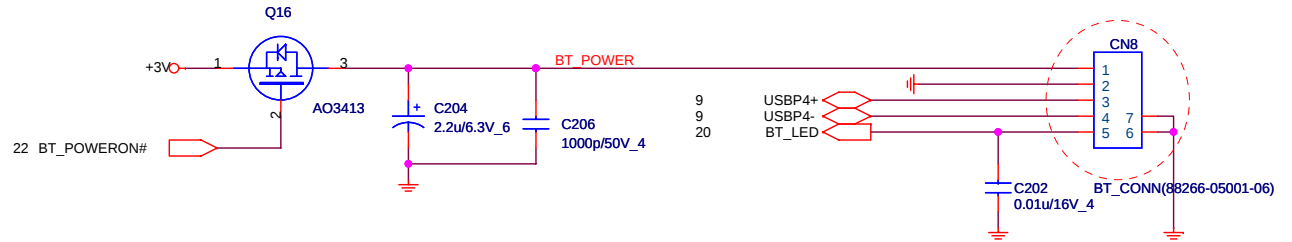
Keyboard (KBC)



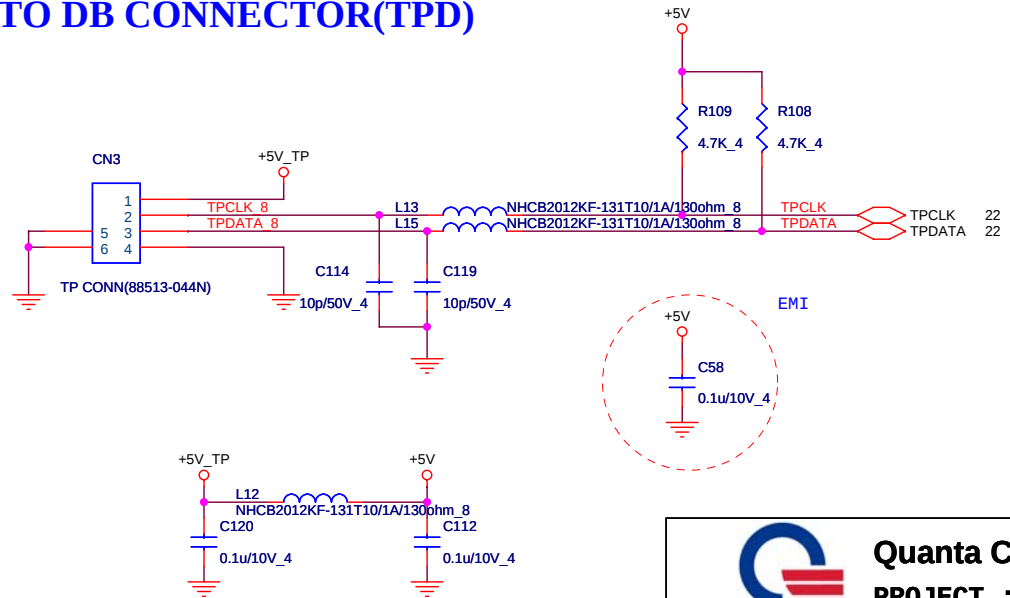
For EMI Reserve Caps for debug



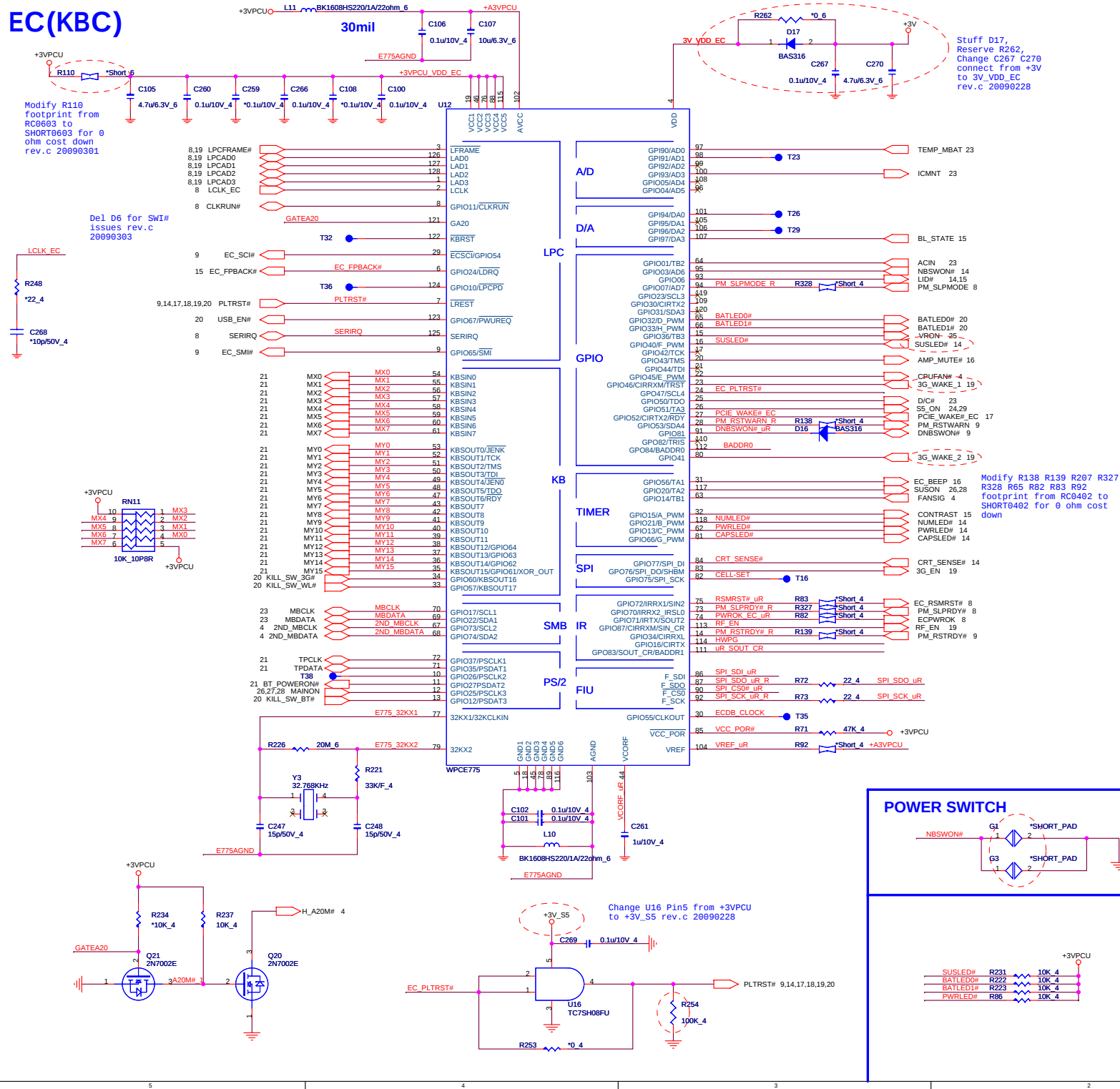
BT CONNECTER(BTM)



TO DB CONNECTOR(TPD)



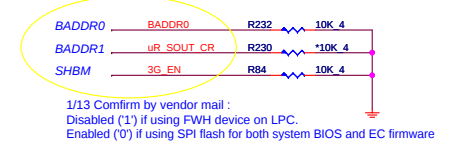
EC(KBC)



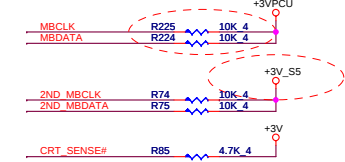
I/O ADDRESS SETTING

	I/O Address	
BADDR1-0	Index	Data
0 0	XOR TREE TEST MODE	
0 1	CORE DEFINED	
1 0	2Eh	2Fh
1 1	164Eh	164Fh

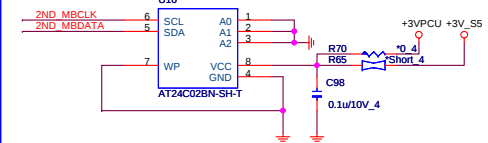
SHBM=0: Enable shared memory with host BIOS



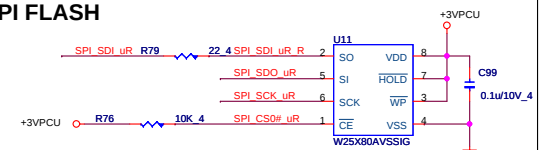
SM BUS PU



ACER ID

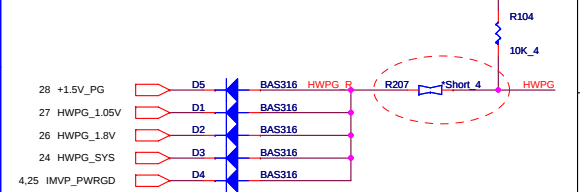


SPI FLASH

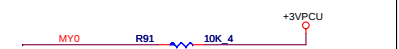


1/13 Confirm by vendor mail :
If the Southbridge enables 'Long Wait Abort' by default, the
flash device should be 50MHz (or faster)

HWPG



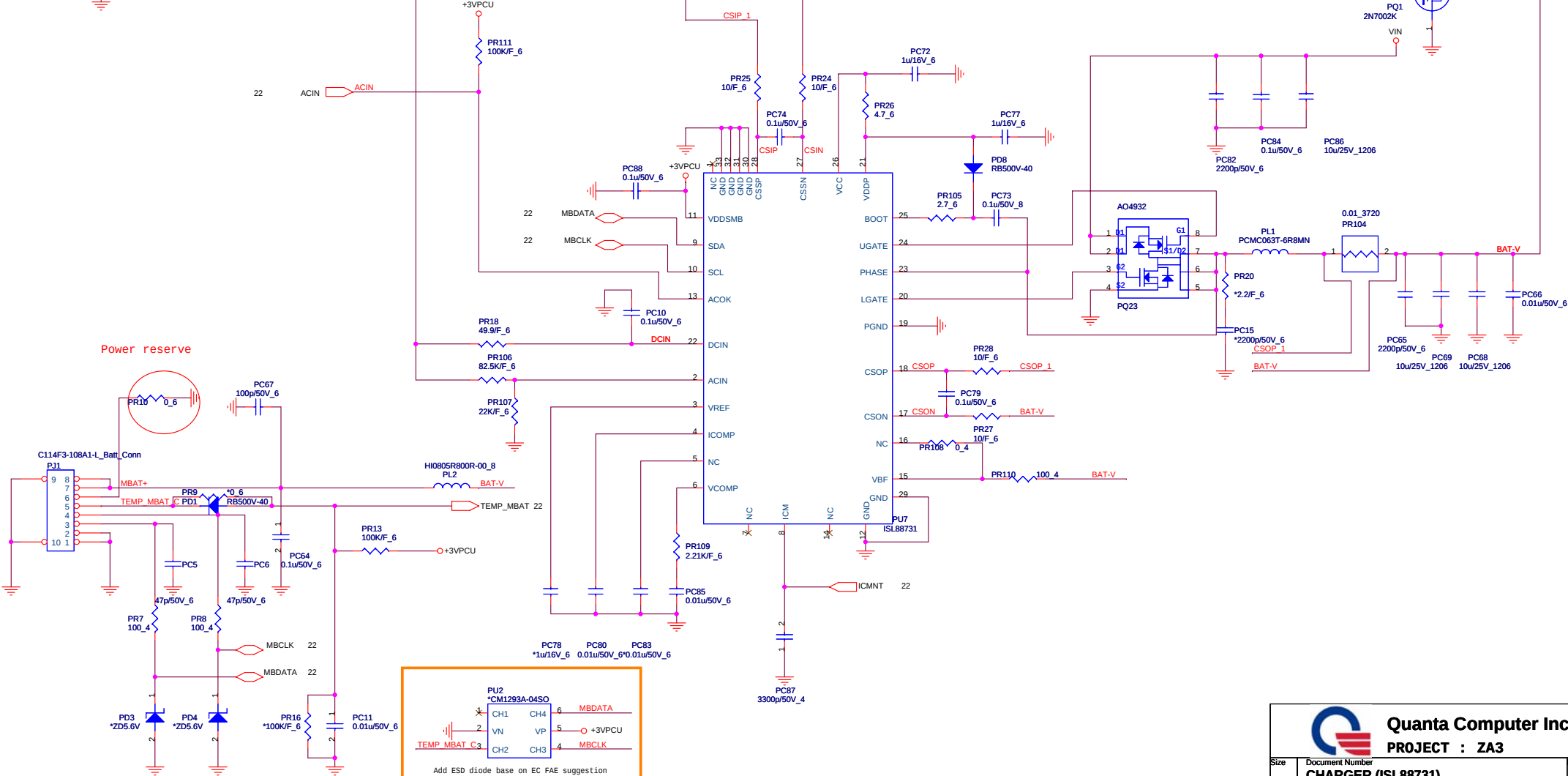
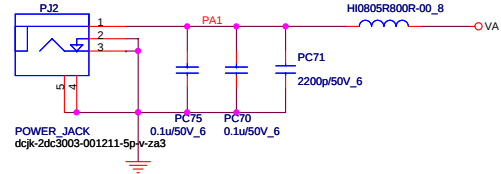
INTERNAL KEYBOARD STRIP SET

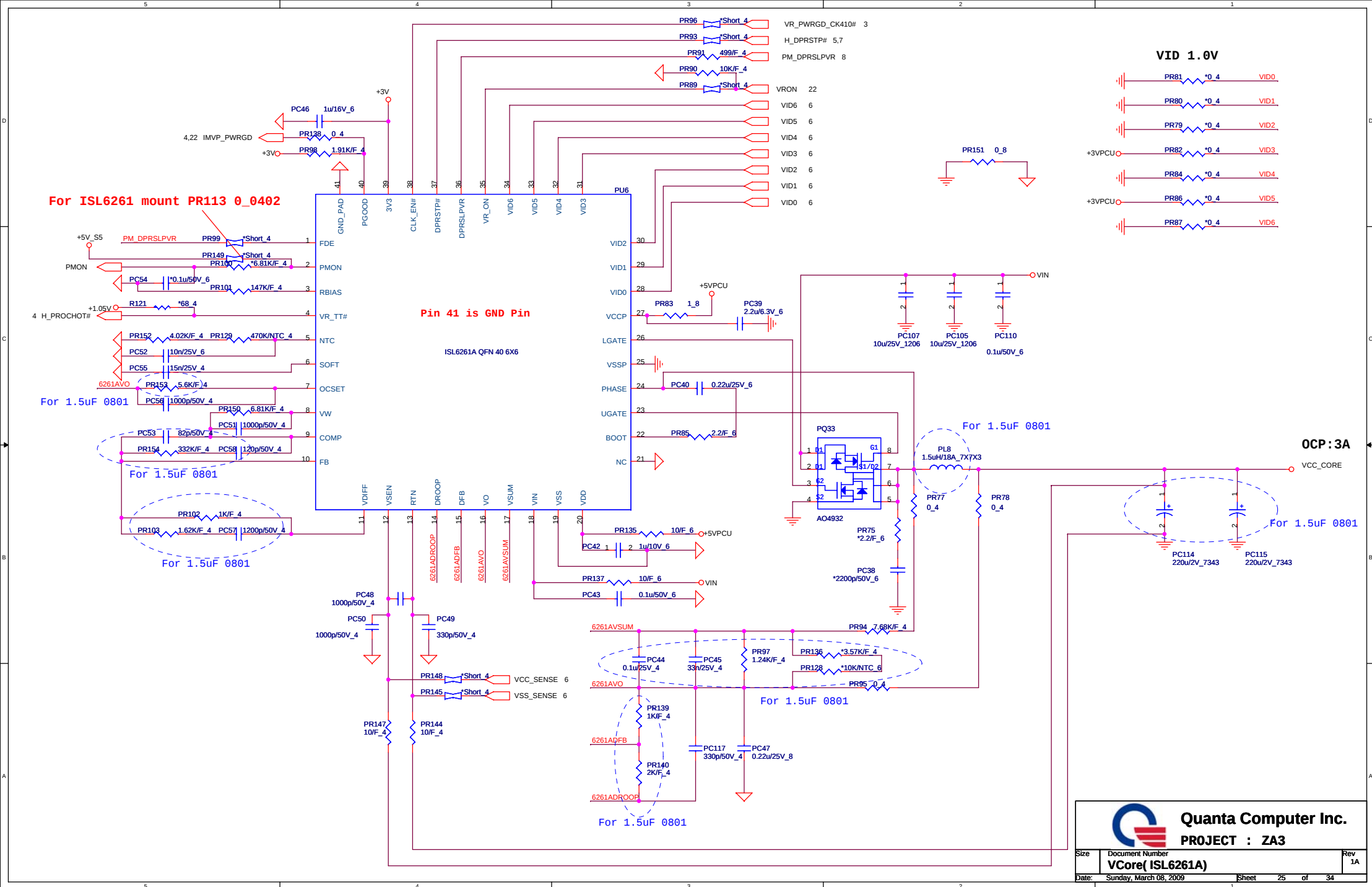


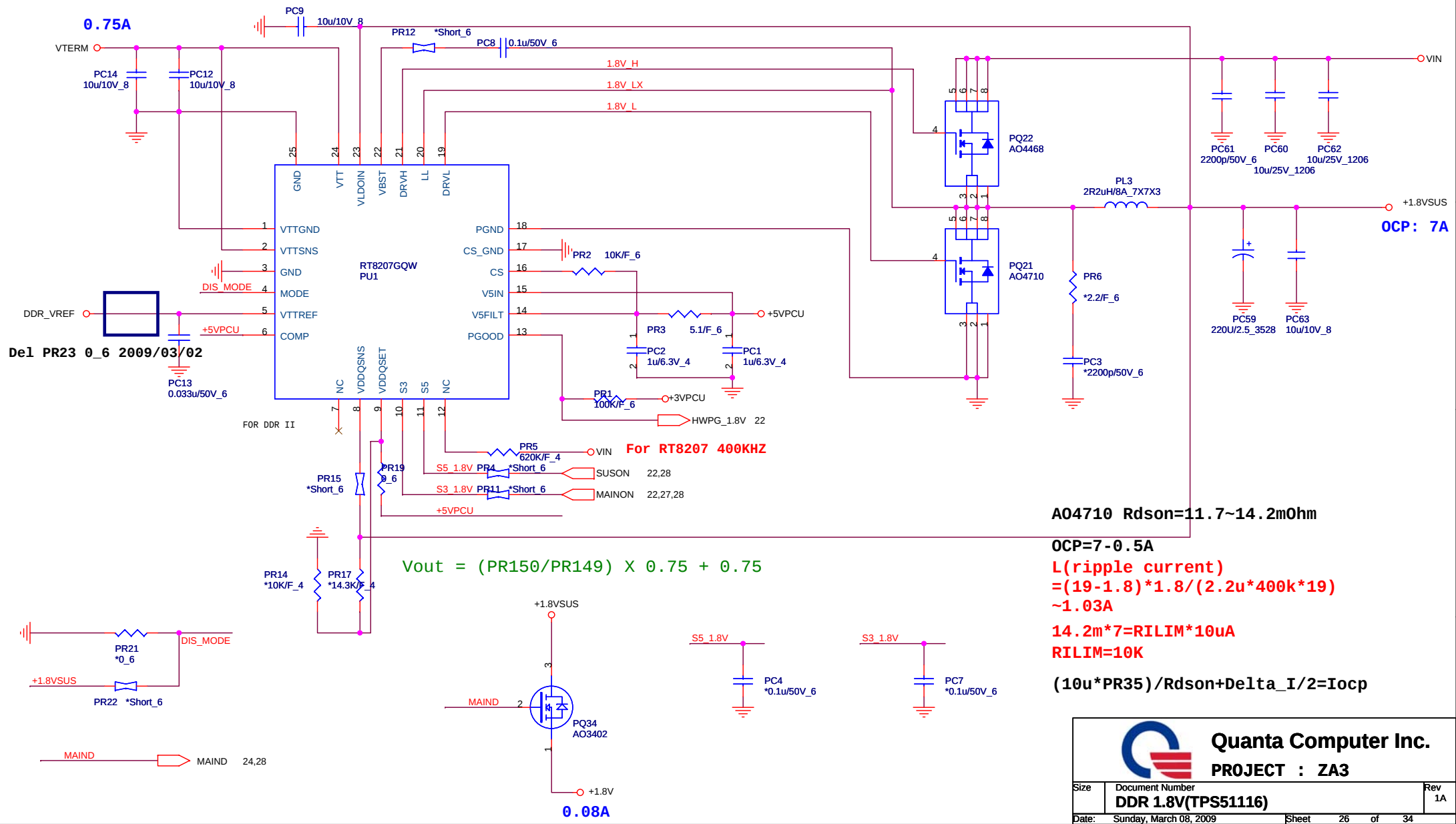
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65W Yellow DFPJ05MR007

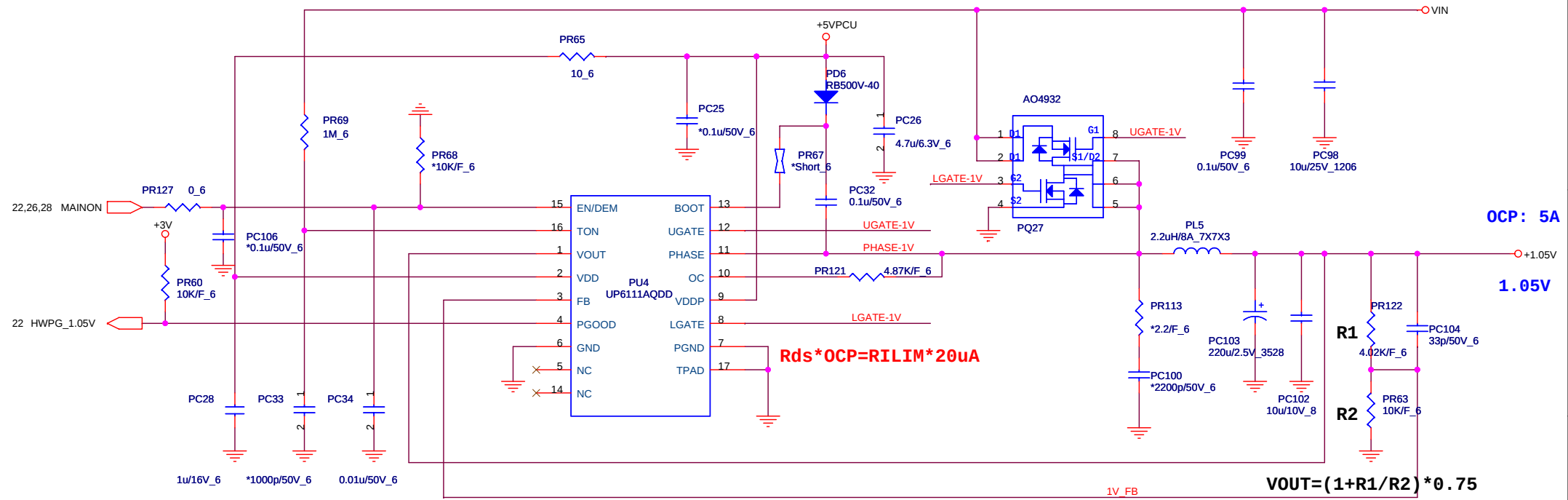


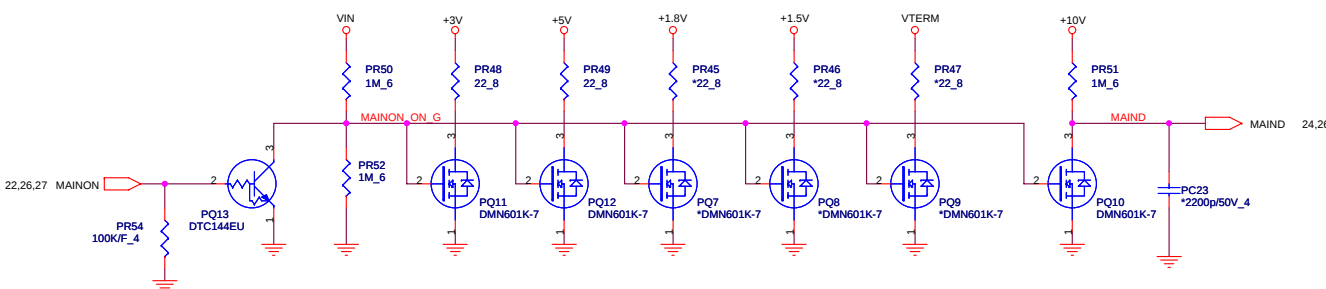
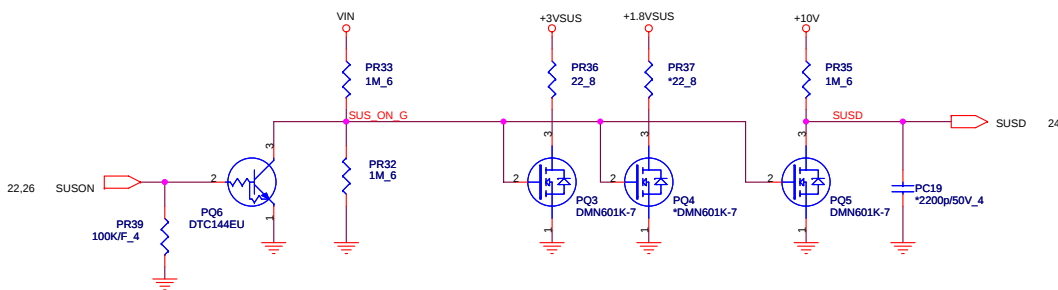
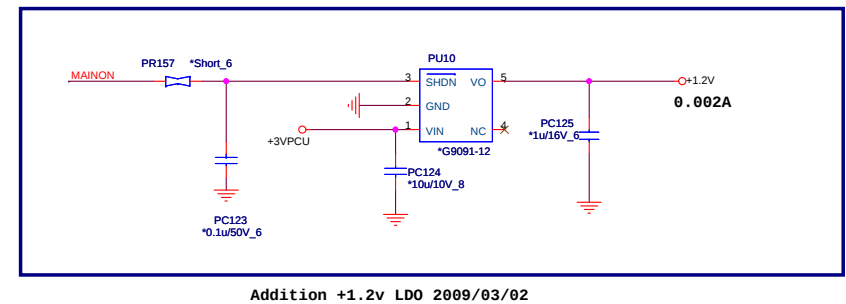
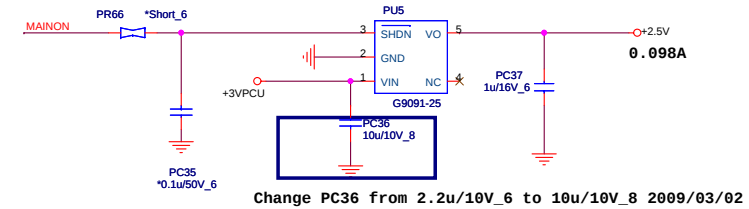
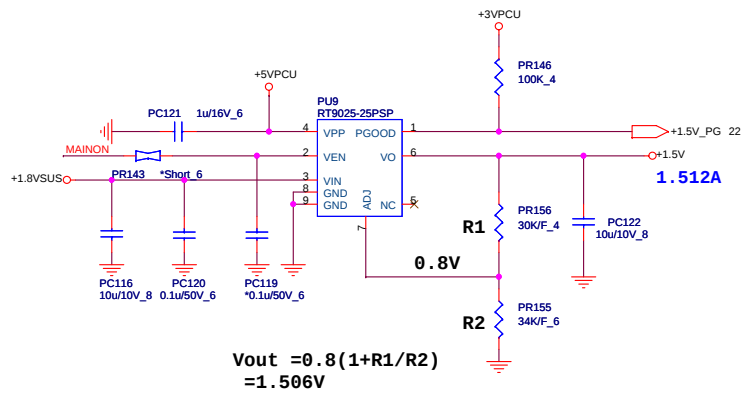


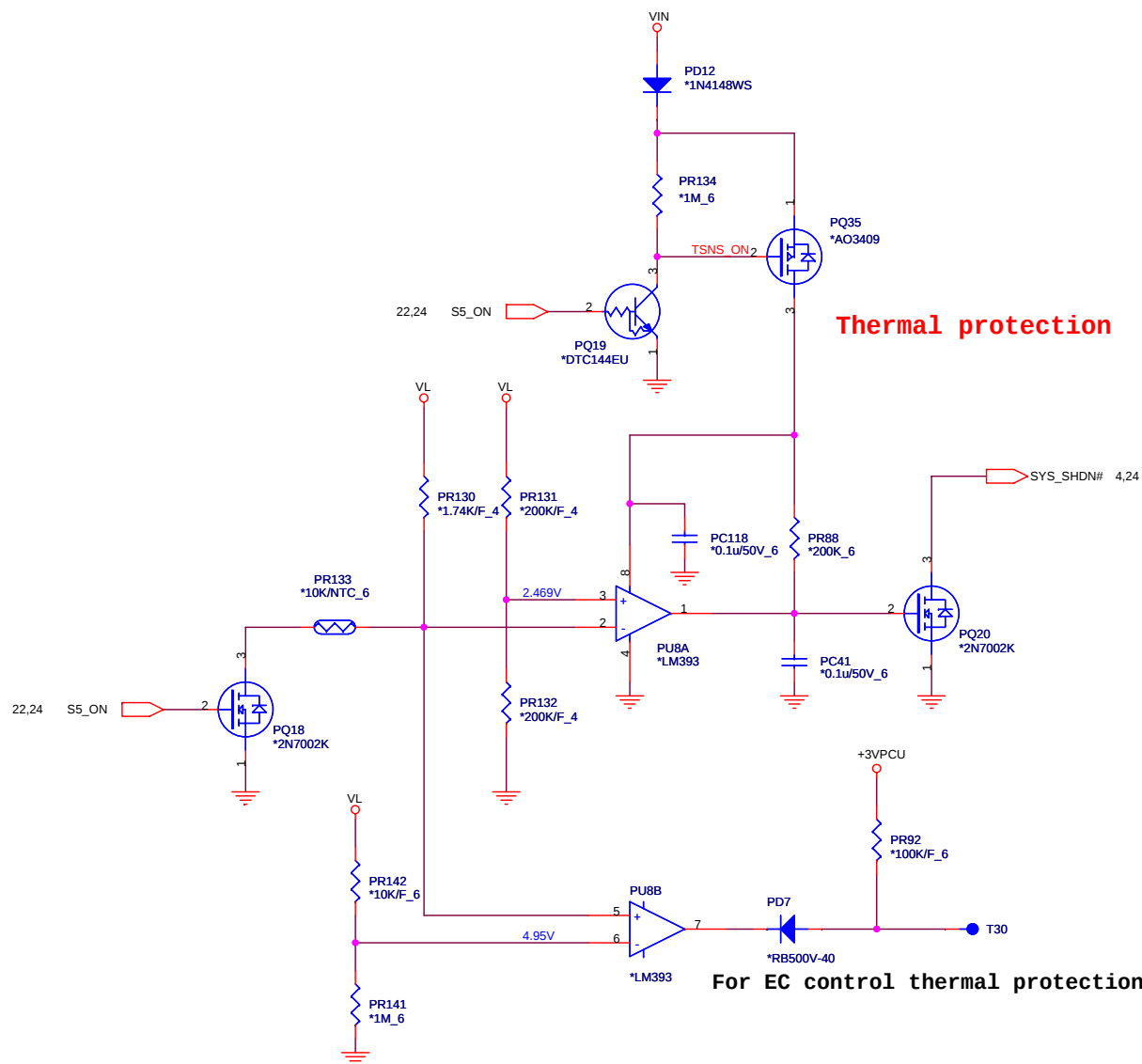


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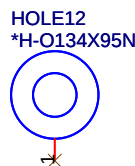
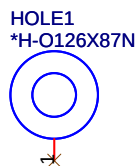
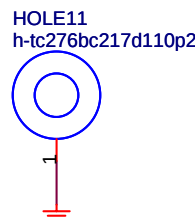
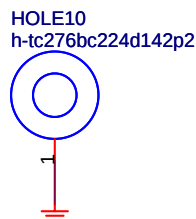
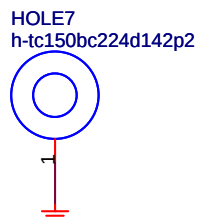
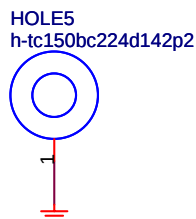
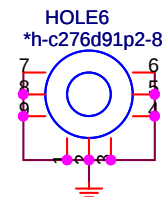
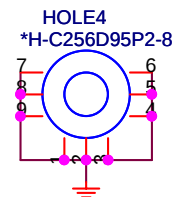
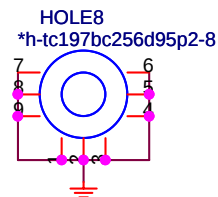
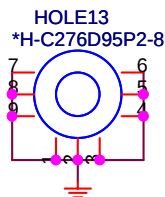
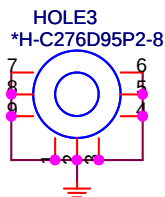
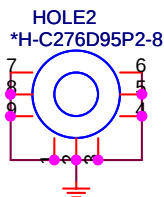




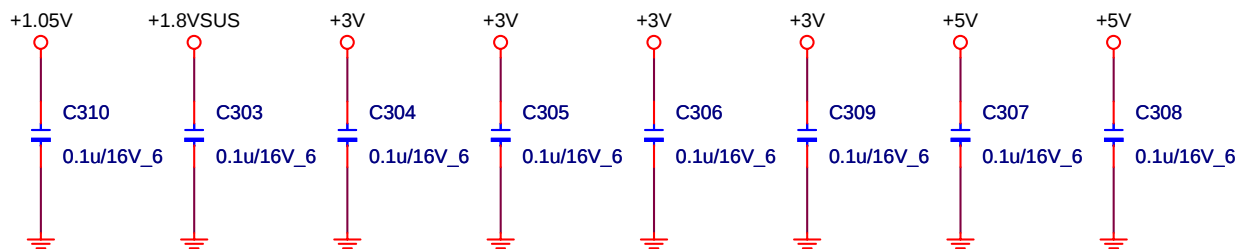
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	Thermal protect	1A
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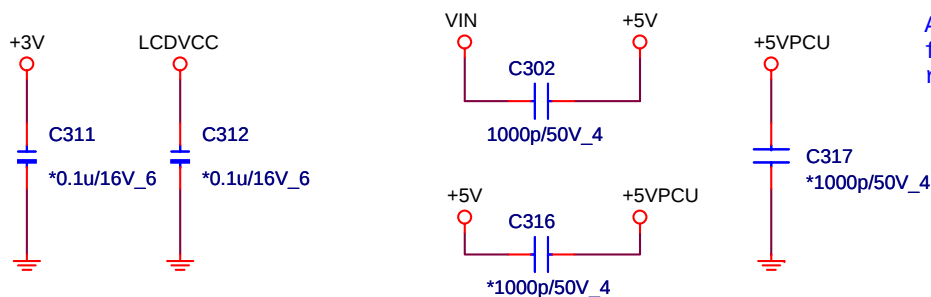
HOLES



EMI



Add C303 C304 C305 C306 C307
C308 for EMI request rev.b
20090206 Add C309 C310 for
EMI request rev.b 20090207

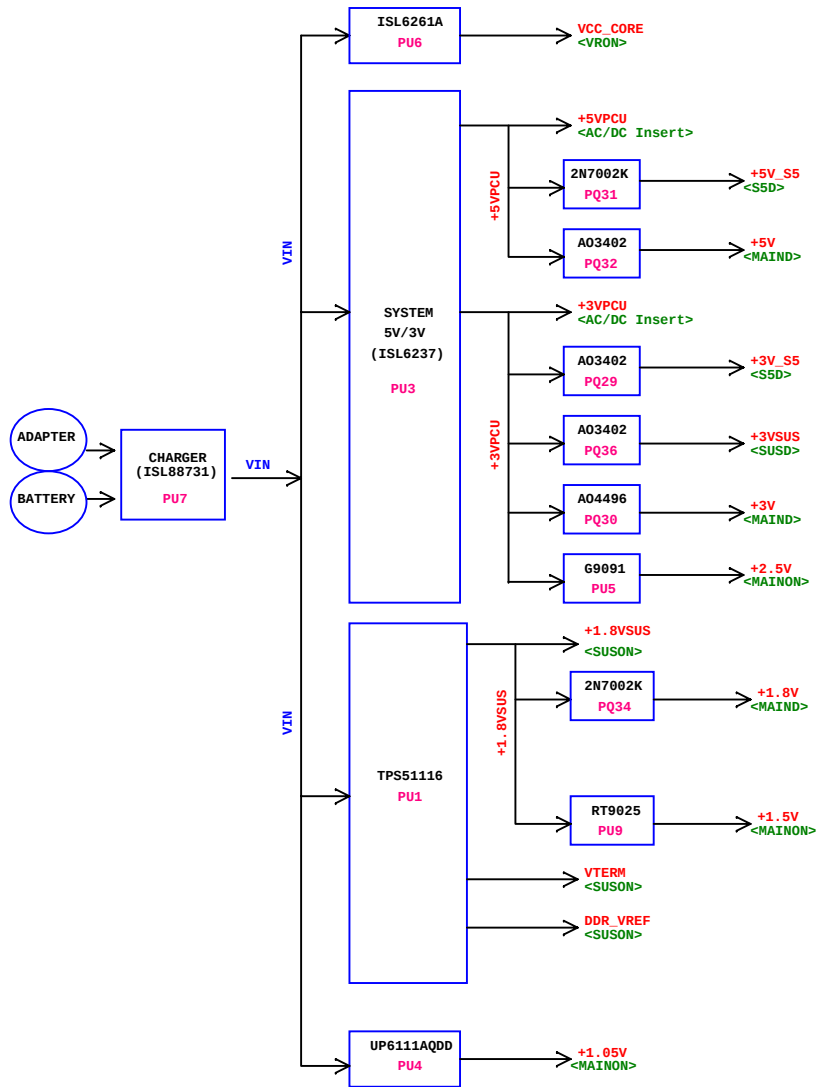


Add C302 C316 C317
for EMI issues
rev.c 20090303

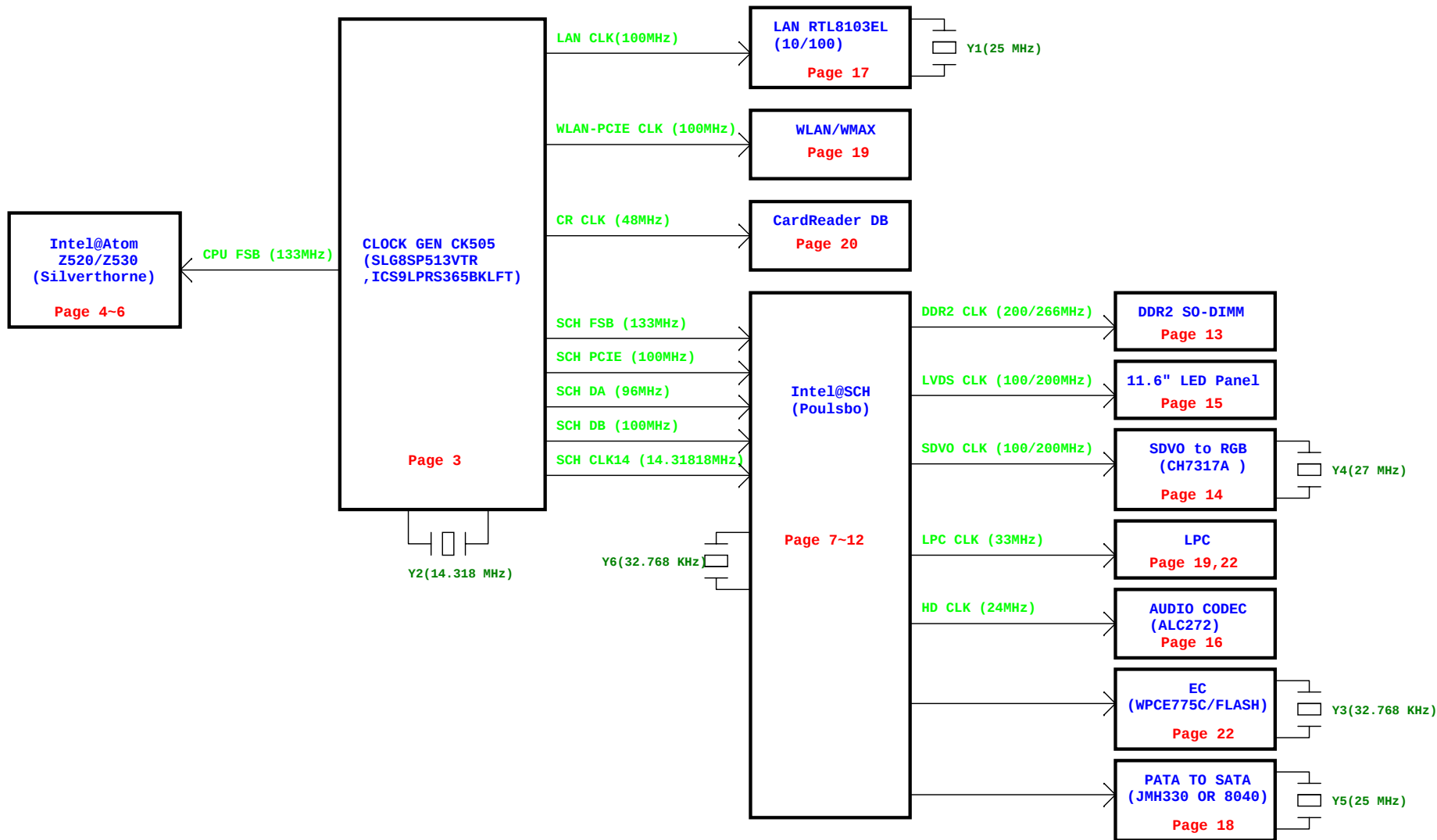


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	HOLE	1A
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POWER	Distribution
VCC_CORE	CPU
+5VPCU	RTC, USB Connector
+5V_S5	SCH Power
+5V	CPU C6-Power Circuit, SCH Power, CRT, LCD, CAMERA ,Audio Code, INT SPK AMP, SATA HDD,Touch Pad
+3VPCU	RTC, LED Power, HALL SENSOR, EC, ID , SPI Flash ,
+3V_S5	SCH USB Power, LAN, ID
+3VSUS	WLAN/WMAX, 3G
+3V	CLK_GEN Power, Thermal Sensor Power, CPU Pull Up Power, SCH Pull Up Power, SCH Power, DDRII Power, SDVO to CRT Power, LCD Power, INT SPK AMP, PATA To SATA Bridge, SATA, WLAN/WMAX, 3G, Card Reader, BT, EC,
+2.5V	SDVO to CRT
+1.8VSUS	SCH Power, DDRII S0-DIMM
+1.8V	PATA To SATA Bridge
+1.5V	CPU, SCH, WLAN/WMAX, 3G
VTERM	DDRII S0-DIMM
DDR_VREF	DDRII S0-DIMM
+1.05V	CLK_GEN, CPU, SCH,



Model	REV	DATE	CHANGE LIST	NOTE
ZA3	A1A	20090107	PAGE16 : Reverse C301 R322 U19 R323 R324 for SPK AMP Power	ECN Release
		20090112	PAGE23 : Change PJ1 P/N and Footprint	
		20090113	PAGE18 : Del RN20 and add RN21 RN22 for HDD issues	
			PAGE18 : Add R325 for JMH330 XTAL issues	
			PAGE21 : Change CN4 P/N from DFFC24FR023 to DFFC24FR017	
			PAGE21 : Change CN4 footprint	
			PAGE20 : Change CN5 P/N from DFFC14FR080 to DFFC14FR047	
			PAGE20 : Change CN6 P/N from DFFC12FR293 to DFFC12FR019	
			PAGE17 : Change CN2 P/N from DFFC12FR293 to DFFC12FR019	
			PAGE20 : Change CN5 footprint from BL121-14R-TAND-14P-L-BU1 to af714l-n2g1x-14p-l	
			PAGE19 : Change ESD1 value to U20	
			PAGE16 : Change CN7 P/N from DFHS04FS969 to DFHD04MRA75	
			PAGE16 : Change CN7 footprint from 88460-0401-4p-l to 88266-040xx-xxx-4p-l	
			PAGE4 : Change CN7 P/N from DFHS04FS969 to DFHD04MRA75	
			PAGE4 : Change CN7 footprint from 88460-0401-4p-l to 88266-040xx-xxx-4p-r	
			PAGE21 : Change CN8 P/N from DFHS05FS000 to DFHD05MRD98	
			PAGE21 : Change CN8 footprint from 88460-0501-5P-L to 88266-0500x-5p-l	
			PAGE6 : Del Q10 R138R139 for modify +1.05V_C6_OFF circuit	
			PAGE6 : Change R168 P/N from CS41002FB28 to CS31002JB28 for modify +1.05V_C6_OFF circuit	
			PAGE6 : Add R326 for modify +1.05V_C6_OFF circuit	
			PAGE6 : Change R148 P/N from CS41002FB28 to CS33302JB16 for modify +1.05V_C6_OFF circuit	
			PAGE6 : Add Q26 for modify +1.05V_C6_OFF circuit	
		20090114	PAGE22 : Add R138 R139 R327 R328 for power sequence debug	
			PAGE5 : Add T54 T56 T57 T58 for power sequence debug	
			PAGE4 : Add T55 T59 for power sequence debug	
			PAGE14 : Change Y4 footprint from XTAL-3_2X2_5-2_3X1_9 to xtl-5x3_2-3_7 for cost down issues	
			PAGE14 : Change Y4 P/N from BG627000011 to BG627000505 for cost down issues	
			PAGE17 : Change U1 P/N from AL08103EB00 to AL008103B00	
		20090115	PAGE15 : Change CN1 footprint from MSC-RB30-5-FG-30P-L to msc-rb30-5-fg-30p-l-za3 for ZA3 A-test SMT issues	
			PAGE19 : Change JSIM1 footprint from SIM-CE01X-3-14P to sim-ce01x-3-14p-za3 for ZA3 A-test SMT issues	
			PAGE19 : Change CN18 footprint from mipcie-88956-5204-52p-ruv-v to mipcie-88956-5204-52p-ruv-v-za3 for ZA3 A-test SMT issues	
			PAGE19 : Change CN19 footprint from mipcie-88956-5204-52p-ruv-v to mipcie-88956-5204-52p-ruv-v-za3 for ZA3 A-test SMT issues	
			PAGE20 : Change CN11 footprint from usb-020173mr004s555zl-4p-r-v to usb-020173mr004s555-4p-r-v-za3 for ZA3 A-test SMT issues	
			PAGE20 : Change CN14 footprint from usb-020173mr004s555zl-4p-r-v to usb-020173mr004s555-4p-r-v-za3 for ZA3 A-test SMT issues	
			PAGE23 : Change PJ2 footprint from dcjk-2dc3003-001211-5p to dcjk-2dc3003-001211-5p-v-za3 for ZA3 A-test SMT issues	
			PAGE23 : Change PR104 footprint from RC3720 to rc3720-0_8h for ZA3 A-test SMT issues	
			PAGE23 : Change PR112 footprint from RC3720 to rc3720-0_8h for ZA3 A-test SMT issues	
			PAGE14 : Change U9 footprint from QFN64-8X8-4-65P-0_85H to qfn64-8X8-4-65p-0_85h-za3 for ZA3 A-test SMT issues	
			PAGE23 : Change PU7 footprint from QFN28-5X5-5-33P to qfn28-5x5-5-33p-za3 for ZA3 A-test SMT issues	
			PAGE22 : Change U12 footprint from LQFP128-16X16-4 to lqfp128-16x16-4-za3 for ZA3 A-test SMT issues	
			PAGE23 : Change PJ1 footprint from bat-c144f8-108a1-l-8p-l-v-zg8 to bat-c144f8-108a1-l-8p-l-v-za3 for ZA3 A-test SMT issues	
			PAGE30 : Change HOLE8 HOLE9 HOLE10 footprint	
			PAGE16 : Modify SPK circuit	
		20090116	PAGE21 : Add CN8 PIN6 PIN7 to GND	
			PAGE30 : Modify HOLE8 HOLE9 HOLE10 symbol	
			PAGE21 : Change CN3 footprint from BL123-04R-4P-R-BL5 to 88513-0401-4p-r	
			PAGE21 : Change CN3 P/N	
		20090117	PAGE16 : Change CN7 P/N from DFHS04FS969 to DFHD04MRA75	
			PAGE4 : Change CN9 P/N from DFHS04FS969 to DFHD04MRA75	
		20090119	PAGE23 : stuff PR10 for Battery issues	
		20090121	PAGE22 : Modify SUSLED# from GPIO30 to GPIO40	
			PAGE27 : Change PL5 P/N from DC-33D5M000 to DC-2280M002	
		20090129	PAGE15 : Change C209 P/N from CH62202Z233 to CH52202MA91	
			PAGE15 : Change C209 footprint from CC1206 to CC0805	
			PAGE19 : Change CN18 P/N from DG052000031 to DFHS52FR025 for cost issues	
			PAGE19 : Change CN19 P/N from DG052000031 to DFHS52FR025 for cost issues	
			PAGE20 : Add R329 and C302 for EMI 48MHz issues	
			PAGE19 : Change C182 P/N from CH44702K912 to CH4472K9B00	
		20090205	PAGE8 : Add T60 T61 T62 T63 test point for Boundary Scan	
			PAGE4 : Modify JETC pins for Boundary Scan	
			PAGE9 : Modify JETC pins for Boundary Scan	
			PAGE16 : Modify CN7 pin5 pin6 for ESD issues	
			PAGE14 : Change CN10 P/N form DFWF20MS000 to DFWF20MS002	
			PAGE14 : Change CN10 footprint form 88442-2001-20p-luv to 87242-2001-20p-luv	
			PAGE8 : No stuff C160 for C6 issues	
		20090206	PAGE15 : Add R255 for EMI request	

Model	REV	DATE	CHANGE LIST	NOTE
ZA3	B1A	20090206	PAGE16 : Reverse C301 R322 U19 R323 R324 for SPK AMP Power	ECN Release
		20090207	PAGE30 : Add C303 C304 C305 C306 C307 C308 for EMI Request	
		20090209	PAGE15 : No stuff R208 for EC not use BL_STATE rev.b 20090207	
		20090210	PAGE30 : C309 C310 for EMI Request	
	C1A	20090207	PAGE4 : Change R98 R87 R97 P/N from CS05102FB09 to CS05602JB17 rev.b 20090207	
		20090207	PAGE9 : Change R260 R259 R256 P/N from CS05102FB09 to CS05602JB17	
		20090207	PAGE9 : Change R257 P/N from CS02702JB21 to CS05602JB17 rev.b 20090207	
		20090209	PAGE8 : Change T60 T61 T62 T63 footprint from TP3075 to TP3050	
		20090210	PAGE8 : Modify HOLE10 HOLE5 HOLE7 footprint	
		20090210	PAGE15 : Change U8 P/N from AL005243000 to AL005243001	
		20090210	PAGE16 : Change R181 R176 P/N from CS07502FB17 to CS05102JB35	
		20090211	PAGE7 ~ PAGE12 : Change U15 P/N from AJSLGFQ0T02 to AJ0QV230T01	
		20090211	PAGE30 : C311 C312 for EMI Request	
		20090212	PAGE30 : Modify CN10 P/N and footprint for EMI request	
		20090212	PAGE16 : Change R204, R187, R313, R304 P/N from CS32003F933 to CS33603F911	
		20090212	PAGE17 : Change C4 C5 P/N from CH02706JB06 to CH03306JBD7 for vender suggest	
		20090213	PAGE3 : Change C42 C43 P/N from CH02706JB06 to CH03306JBD7 for vender suggest	
		20090213	PAGE18 : Change C250 C251 P/N from CH02206JB08 to CH02706JB06 for vender suggest	
		20090213	PAGE16 : Change R164 P/N from CS21002JB34 to CS22002JB02 for Ben check	
		20090213	PAGE16 : Change R167 P/N from CS00002JB38 to CS33602JB17 for Ben check	
		20090228	PAGE11 : Change C163 C136 connect SCH_VCCSUS3 power net	
		20090301	PAGE22 : Change U16 Pin5 from +3VPCU to +3V_S5	
		20090301	PAGE22 : Stuff D17, Reserve R262, Change C267 C270 connect from 3V_VDD_EC to +3V	
		20090301	PAGE6 : Modify R326 from 10K to 100K and pull up +3V and Change R168 from 10K to 100K	
		20090301	PAGE21 : Modify CN8 footprint and pin define	
		20090301	PAGE18 : Modify 8040 circuit to 88SA8052 add L22 R330 R331 R99 R339	
		20090301	PAGE4 : Modify R150 from CPU side to SCH side	
		20090301	PAGE4 : Change R88 P/N from CS05602JB17 to CS11202JB21	
		20090301	PAGE4 : Change R81 P/N from CS00002JB38 to CS02402JB11	
		20090301	PAGE6 : Change R100 R101 P/N from CS11002FB22 to CS11002JB32	
		20090301	PAGE13 : Add R112 R332 of RAM RST issues for intel suggest	
		20090301	PAGE15 : Change R215 P/N from CS41002JB20 to CS41002FB28	
		20090301	PAGE8 : Add R333 R334 R335 R336 for LPC AD0-AD3	
		20090301	PAGE8 : Change C233 C231 C243 C240 C239 C238 C237 C235 from SDVO chip side to SCH side	
		20090301	PAGE3 : Change R43 P/N from CS00002JB38 to CS31002JB28	
		20090301	PAGE9 : Change R186 R184 R309 R296 P/N from CS31002JB28 to CS21002JB34	
		20090301	PAGE9 : Del RN8 and Add R337 R338 to SCH SMBUS	
		20090301	PAGE15 : Modify R210 R23 footprint from RC0402 to SHORT0402 for 0 ohm cost down	
		20090301	PAGE16 : Modify R275 footprint from RC0402 to SHORT0402 for 0 ohm cost down	
		20090301	PAGE22 : Modify R138 R139 R207 R327 R328 R65 R82 R83 R92 footprint from RC0402 to SHORT0402 for 0 ohm cost down	
		20090301	PAGE10 : Modify R111 footprint from RC0402 to SHORT0402 for 0 ohm cost down	
		20090301	PAGE19 : Modify R160 R161 R162 R178 R179 R180 footprint from RC0402 to SHORT0402 for 0 ohm cost down	
		20090301	PAGE3 : Modify R39 R36 footprint from RC0402 to SHORT0402 for 0 ohm cost down	
		20090301	PAGE22 : Modify R110 footprint from RC0603 to SHORT0603 for 0 ohm cost down	
		20090301	PAGE11 : Modify R126 footprint from RC0603 to SHORT0603 for 0 ohm cost down	
		20090301	PAGE16 : Modify R144 R149 R170 R183 R246 R251 R197 R198 R199 R200 footprint from RC0603 to SHORT0603 for 0 ohm cost down	
		20090302	PAGE16 : Modify R168 P/N from CS31002JB28 to CS41002JB20	
		20090302	PAGE23 : Modify PJ1 footprint from bat-c144f8-108a1-l-8p-l-v-za3 to bat-c144f8-108a1-l-8p-l-v for SMT issues	
		20090303	PAGE14 : Add C313 C314 C315 for EMI issues	
		20090303	PAGE16 : Add R340 for EC PCBEEP	
		20090303	PAGE3 : Del R27 for CR DB +3VSUS issues	
		20090303	PAGE20 : Del R329 C302 for CR DB +3VSUS issues and modify CN5 pin12 to +3VSUS	
		20090303	PAGE6 : Add and revrse Q27 R329 for C6 circuit	
		20090303	PAGE19 : Add C318 for LPC issues	
		20090303	PAGE30 : Add C302 C316 C317 for EMI issues	
		20090303	PAGE13 : Del RN4 and Add R341 R342 for RAM issues	
		20090303	PAGE9 : Stuff R297 for SMI#	
		20090303	PAGE9 : No stuff R239 for SWI#	
		20090303	PAGE22 : Del D6 for SWI# issues	
		20090304	PAGE9 : Change R297 from +3V_S5 to +3V for SMI#	
		20090304	PAGE22 : Del SWI# net and Add test point T36	
		20090304	PAGE19 : No stuff C182 and change P/N from CH4472K9B00 to CH4471Z3B07	
		20090305	PAGE16 : Change U18 P/N from AL001453000 to AL001454001	
		20090305	PAGE19 : Change CN18 CN19 P/N from DFHS52FR025 to DG052000031	
		20090305	PAGE15 : Change CN1 P/N from DFHS30FR299 to DFHS30FR014 for SMT issues	
		20090305		
		20090305		
		20090305		